

DATA SHEET

PCF8579

LCD column driver for dot matrix
graphic displays

Product specification
Supersedes data of 1996 Oct 25
File under Integrated Circuits, IC12

1997 Apr 01

LCD column driver for dot matrix graphic displays

PCF8579

CONTENTS	10	LIMITING VALUES	
1	FEATURES	11	HANDLING
2	APPLICATIONS	12	DC CHARACTERISTICS
3	GENERAL DESCRIPTION	13	AC CHARACTERISTICS
4	ORDERING INFORMATION	14	APPLICATION INFORMATION
5	BLOCK DIAGRAM	15	CHIP DIMENSIONS AND BONDING PAD LOCATIONS
6	PINNING	16	CHIP-ON GLASS INFORMATION
7	FUNCTIONAL DESCRIPTION	17	PACKAGE OUTLINES
7.1	Multiplexed LCD bias generation	18	SOLDERING
7.2	Power-on reset	18.1	Introduction
7.3	Timing generator	18.2	Reflow soldering
7.4	Column drivers	18.3	Wave soldering
7.5	Display RAM	18.3.1	LQFP
7.6	Data pointer	18.3.2	VSO
7.7	Subaddress counter	18.3.3	Method (LQFP and VSO)
7.8	I ² C-bus controller	18.4	Repairing soldered joints
7.9	Input filters	19	DEFINITIONS
7.10	RAM access	20	LIFE SUPPORT APPLICATIONS
7.11	Display control	21	PURCHASE OF PHILIPS I ² C COMPONENTS
7.12	TEST pin		
8	I ² C-BUS PROTOCOL		
8.1	Command decoder		
9	CHARACTERISTICS OF THE I ² C-BUS		
9.1	Bit transfer		
9.2	Start and stop conditions		
9.3	System configuration		
9.4	Acknowledge		



LCD column driver for dot matrix graphic displays

PCF8579

1 FEATURES

- LCD column driver
- Used in conjunction with the PCF8578, this device forms part of a chip set capable of driving up to 40960 dots
- 40 column outputs
- Selectable multiplex rates; 1 : 8, 1 : 16, 1 : 24 or 1 : 32
- Externally selectable bias configuration, 5 or 6 levels
- Easily cascadable for large applications (up to 32 devices)
- 1280-bit RAM for display data storage
- Display memory bank switching
- Auto-incremented data loading across hardware subaddress boundaries (with PCF8578)
- Power-on reset blanks display
- Logic voltage supply range 2.5 to 6 V
- Maximum LCD supply voltage 9 V
- Low power consumption
- I²C-bus interface
- TTL/CMOS compatible
- Compatible with most microcontrollers
- Optimized pinning for single plane wiring in multiple device applications (with PCF8578)
- Space saving 56-lead plastic mini-pack and 64-pin plastic low profile quad flat package
- Compatible with chip-on-glass technology
- I²C-bus address: 011110 SA0.

2 APPLICATIONS

- Automotive information systems
- Telecommunication systems
- Point-of-sale terminals
- Computer terminals
- Instrumentation.

3 GENERAL DESCRIPTION

The PCF8579 is a low power CMOS LCD column driver, designed to drive dot matrix graphic displays at multiplex rates of 1 : 8, 1 : 16, 1 : 24 or 1 : 32. The device has 40 outputs and can drive 32 × 40 dots in a 32 row multiplexed LCD. Up to 16 PCF8579s can be cascaded and up to 32 devices may be used on the same I²C-bus (using the two slave addresses). The device is optimized for use with the PCF8578 LCD row/column driver. Together these two devices form a general purpose LCD dot matrix driver chip set, capable of driving displays of up to 40960 dots. The PCF8579 is compatible with most microcontrollers and communicates via a two-line bidirectional bus (I²C-bus). To allow partial V_{DD} shutdown the ESD protection system of the SCL and SDA pins does not use a diode connected to V_{DD}. Communication overheads are minimized by a display RAM with auto-incremented addressing and display bank switching.

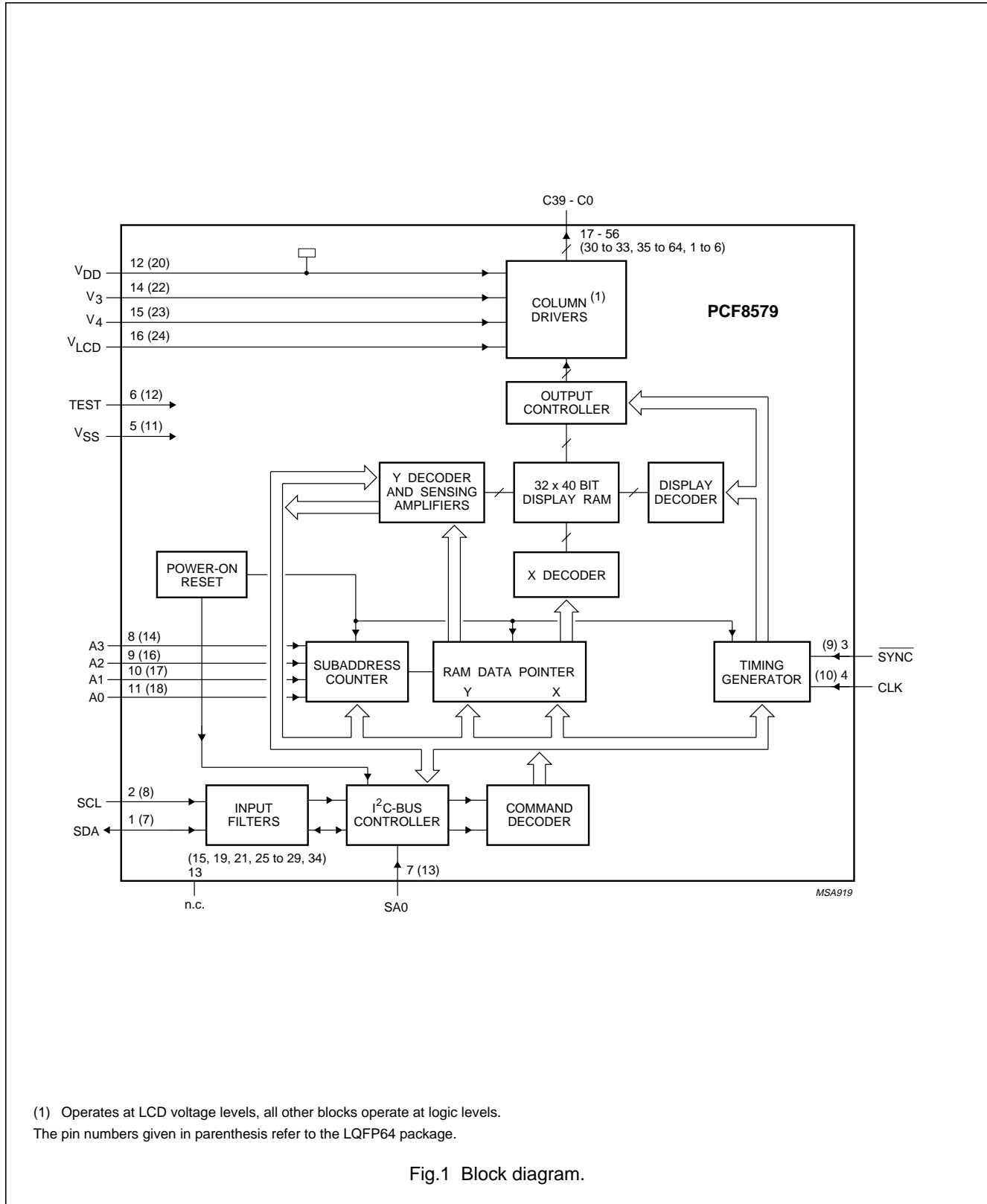
4 ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
PCF8579T	VSO56	plastic very small outline package; 56 leads	SOT190
PCF8579U7	–	chip with bumps on tape	–
PCF8579H	LQFP64	plastic low profile quad flat package; 64 leads; body 10 × 10 × 1.4 mm	SOT314-2

LCD column driver for dot matrix graphic displays

PCF8579

5 BLOCK DIAGRAM



(1) Operates at LCD voltage levels, all other blocks operate at logic levels.
The pin numbers given in parenthesis refer to the LQFP64 package.

Fig.1 Block diagram.

LCD column driver for dot matrix graphic displays

PCF8579

6 PINNING

SYMBOL	PINS		DESCRIPTION
	VSO56	LQFP64	
SDA	1	7	I ² C-bus serial data input/output
SCL	2	8	I ² C-bus serial clock input
$\overline{\text{SYNC}}$	3	9	cascade synchronization input
CLK	4	10	external clock input
V _{SS}	5	11	ground (logic)
TEST	6	12	test pin (connect to V _{SS})
SA0	7	13	I ² C-bus slave address input (bit 0)
A3 to A0	8 to 11	14, 16 to 18	I ² C-bus subaddress inputs
V _{DD}	12	20	supply voltage
n.c.	13 ⁽¹⁾	15, 19, 21, 25 to 29, 34	not connected
V ₃ , V ₄	14 and 15	22 and 23	LCD bias voltage inputs
V _{LCD}	16	24	LCD supply voltage
C39 to C0	17 to 56	30 to 33, 35 to 64 and 1 to 6	LCD column driver outputs

Note

1. Do not connect, this pin is reserved.

LCD column driver for dot matrix graphic displays

PCF8579

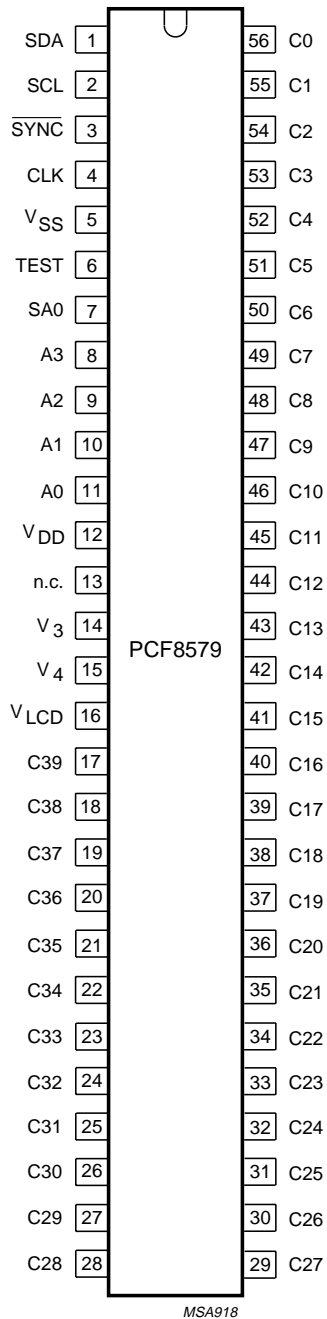


Fig.2 Pin configuration (VSO56).

LCD column driver for dot matrix graphic displays

PCF8579

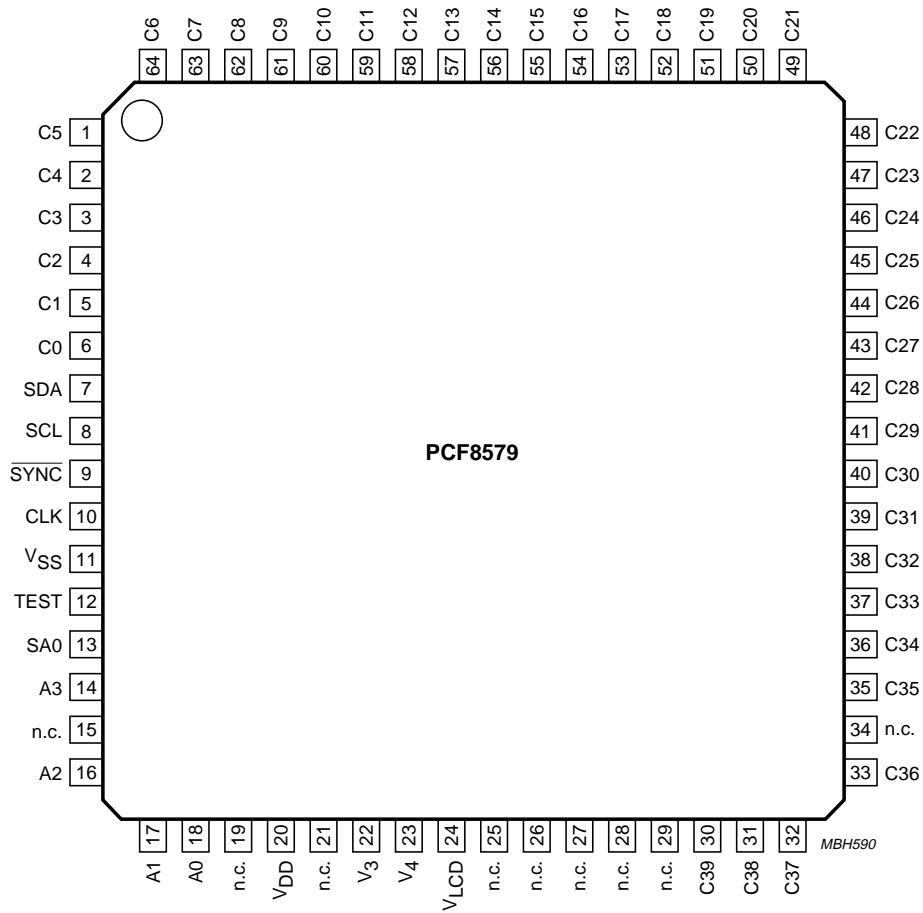


Fig.3 Pin configuration (LQFP64).

LCD column driver for dot matrix graphic displays

PCF8579

7 FUNCTIONAL DESCRIPTION

The PCF8579 column driver is designed for use with the PCF8578. Together they form a general purpose LCD dot matrix chip set.

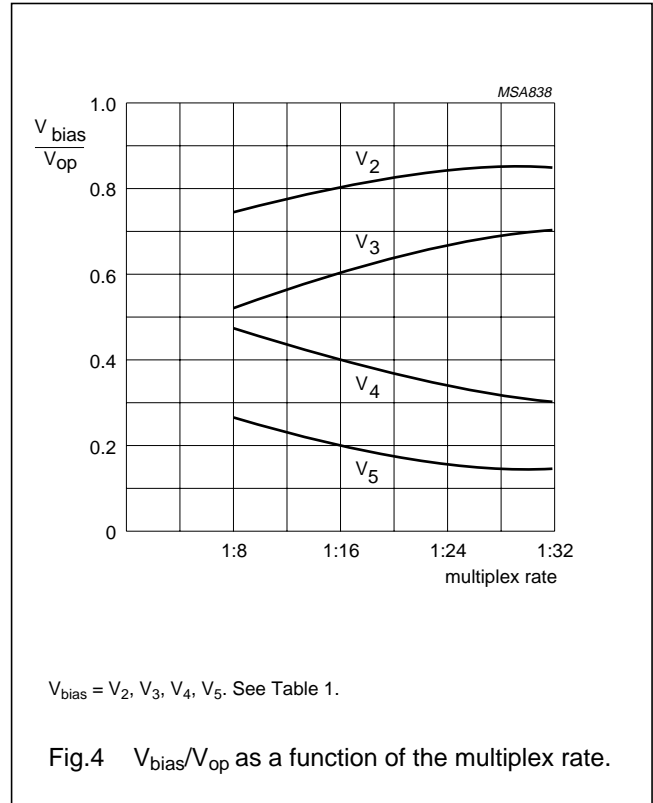
Typically up to 16 PCF8579s may be used with one PCF8578. Each of the PCF8579s is identified by a unique 4-bit hardware subaddress, set by pins A0 to A3. The PCF8578 can operate with up to 32 PCF8579s when using two I²C-bus slave addresses. The two slave addresses are set by the logic level on input SA0.

7.1 Multiplexed LCD bias generation

The bias levels required to produce maximum contrast depend on the multiplex rate and the LCD threshold voltage (V_{th}). V_{th} is typically defined as the RMS voltage at which the LCD exhibits 10% contrast. Table 1 shows the optimum voltage bias levels for the PCF8578/PCF8579 chip set as functions of V_{op} ($V_{op} = V_{DD} - V_{LCD}$), together with the discrimination ratios (D) for the different multiplex rates. A practical value for V_{op} is obtained by equating $V_{off(rms)}$ with V_{th} . Figure 4 shows the first 4 rows of Table 1 as graphs.

Table 1 Optimum LCD bias voltages

PARAMETER	MULTIPLEX RATE			
	1 : 8	1 : 16	1 : 24	1 : 32
$\frac{V_2}{V_{op}}$	0.739	0.800	0.830	0.850
$\frac{V_3}{V_{op}}$	0.522	0.600	0.661	0.700
$\frac{V_4}{V_{op}}$	0.478	0.400	0.339	0.300
$\frac{V_5}{V_{op}}$	0.261	0.200	0.170	0.150
$\frac{V_{off(rms)}}{V_{op}}$	0.297	0.245	0.214	0.193
$\frac{V_{on(rms)}}{V_{op}}$	0.430	0.316	0.263	0.230
$D = \frac{V_{on(rms)}}{V_{off(rms)}}$	1.447	1.291	1.230	1.196
$\frac{V_{op}}{V_{th}}$	3.370	4.080	4.680	5.190



7.2 Power-on reset

At power-on the PCF8579 resets to a defined starting condition as follows:

1. Display blank (in conjunction with PCF8578)
2. 1 : 32 multiplex rate
3. Start bank, 0 selected
4. Data pointer is set to X, Y address 0, 0
5. Character mode
6. Subaddress counter is set to 0
7. I²C-bus is initialized.

Data transfers on the I²C-bus should be avoided for 1 ms following power-on, to allow completion of the reset action.

LCD column driver for dot matrix graphic displays

PCF8579

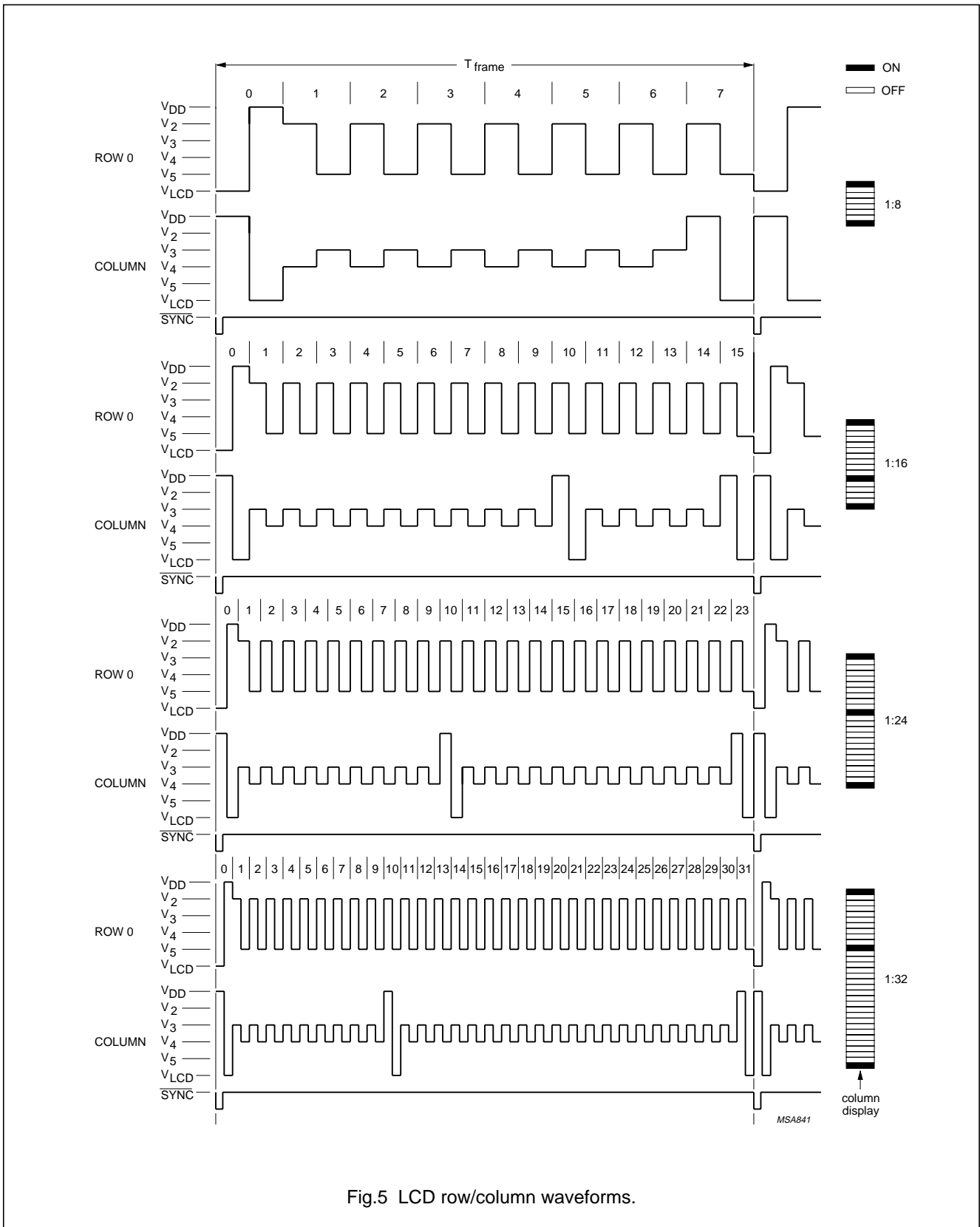
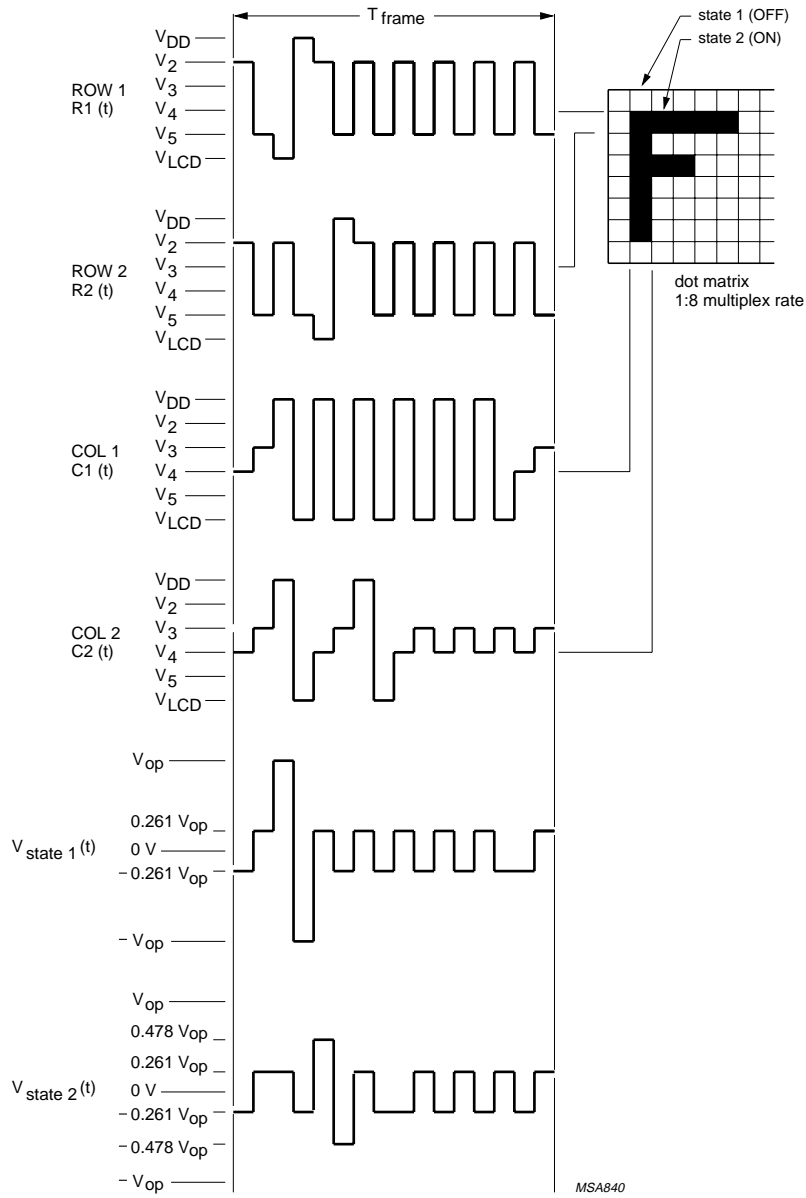


Fig.5 LCD row/column waveforms.

LCD column driver for dot matrix graphic displays

PCF8579



$$V_{state\ 1}(t) = C1(t) - R1(t):$$

$$\frac{V_{on(rms)}}{V_{op}} = \sqrt{\frac{1}{8} + \frac{\sqrt{8}-1}{8(\sqrt{8}+1)}} = 0.430$$

$$V_{state\ 2}(t) = C2(t) - R2(t):$$

$$\frac{V_{off(rms)}}{V_{op}} = \sqrt{\frac{2(\sqrt{8}-1)}{\sqrt{8}(\sqrt{8}+1)^2}} = 0.297$$

general relationship (n = multiplex rate)

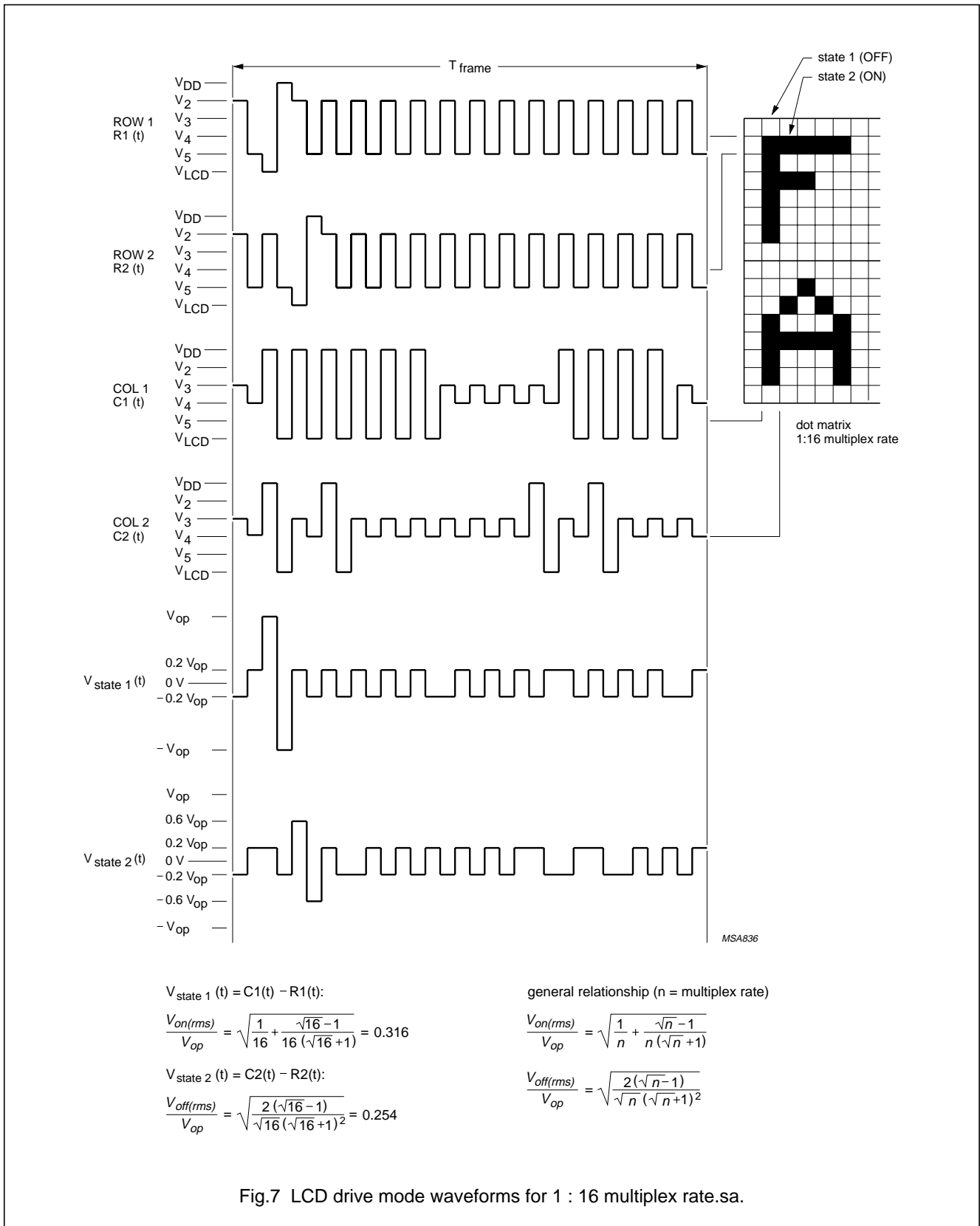
$$\frac{V_{on(rms)}}{V_{op}} = \sqrt{\frac{1}{n} + \frac{\sqrt{n}-1}{n(\sqrt{n}+1)}}$$

$$\frac{V_{off(rms)}}{V_{op}} = \sqrt{\frac{2(\sqrt{n}-1)}{\sqrt{n}(\sqrt{n}+1)^2}}$$

Fig.6 LCD drive mode waveforms for 1 : 8 multiplex rate.

LCD column driver for dot matrix graphic displays

PCF8579



LCD column driver for dot matrix graphic displays

PCF8579

7.3 Timing generator

The timing generator of the PCF8579 organizes the internal data flow from the RAM to the display drivers. An external synchronization pulse $\overline{\text{SYNC}}$ is received from the PCF8578. This signal maintains the correct timing relationship between cascaded devices.

7.4 Column drivers

Outputs C0 to C39 are column drivers which must be connected to the LCD. Unused outputs should be left open-circuit.

7.5 Display RAM

The PCF8579 contains a 32×40 -bit static RAM which stores the display data. The RAM is divided into 4 banks of 40 bytes ($4 \times 8 \times 40$ bits). During RAM access, data is transferred to/from the RAM via the I²C-bus.

7.6 Data pointer

The addressing mechanism for the display RAM is realized using the data pointer. This allows an individual data byte or a series of data bytes to be written into, or read from, the display RAM, controlled by commands sent on the I²C-bus.

7.7 Subaddress counter

The storage and retrieval of display data is dependent on the content of the subaddress counter. Storage and retrieval take place only when the contents of the subaddress counter agree with the hardware subaddress at pins A0, A1, A2 and A3.

7.8 I²C-bus controller

The I²C-bus controller detects the I²C-bus protocol, slave address, commands and display data bytes. It performs the conversion of the data input (serial-to-parallel) and the data output (parallel-to-serial). The PCF8579 acts as an I²C-bus slave transmitter/receiver. Device selection depends on the I²C-bus slave address, the hardware subaddress and the commands transmitted.

7.9 Input filters

To enhance noise immunity in electrically adverse environments, RC low-pass filters are provided on the SDA and SCL lines.

7.10 RAM access

There are three RAM ACCESS modes:

- Character
- Half-graphic
- Full-graphic.

These modes are specified by bits G1 and G0 of the RAM ACCESS command. The RAM ACCESS command controls the order in which data is written to or read from the RAM (see Fig.8).

To store RAM data, the user specifies the location into which the first byte will be loaded (see Fig.9):

- Device subaddress (specified by the DEVICE SELECT command)
- RAM X-address (specified by the LOAD X-ADDRESS command)
- RAM bank (specified by bits Y1 and Y0 of the RAM ACCESS command).

Subsequent data bytes will be written or read according to the chosen RAM access mode. Device subaddresses are automatically incremented between devices until the last device is reached. If the last device has subaddress 15, further display data transfers will lead to a wrap-around of the subaddress to 0.

7.11 Display control

The display is generated by continuously shifting rows of RAM data to the dot matrix LCD via the column outputs. The number of rows scanned depends on the multiplex rate set by bits M1 and M0 of the SET MODE command.

The display status (all dots on/off and normal/inverse video) is set by bits E1 and E0 of the SET MODE command. For bank switching, the RAM bank corresponding to the top of the display is set by bits B1 and B0 of the SET START BANK command. This is shown in Fig.10 This feature is useful when scrolling in alphanumeric applications.

7.12 TEST pin

The TEST pin must be connected to V_{SS} .

LCD column driver for dot matrix graphic displays

PCF8579

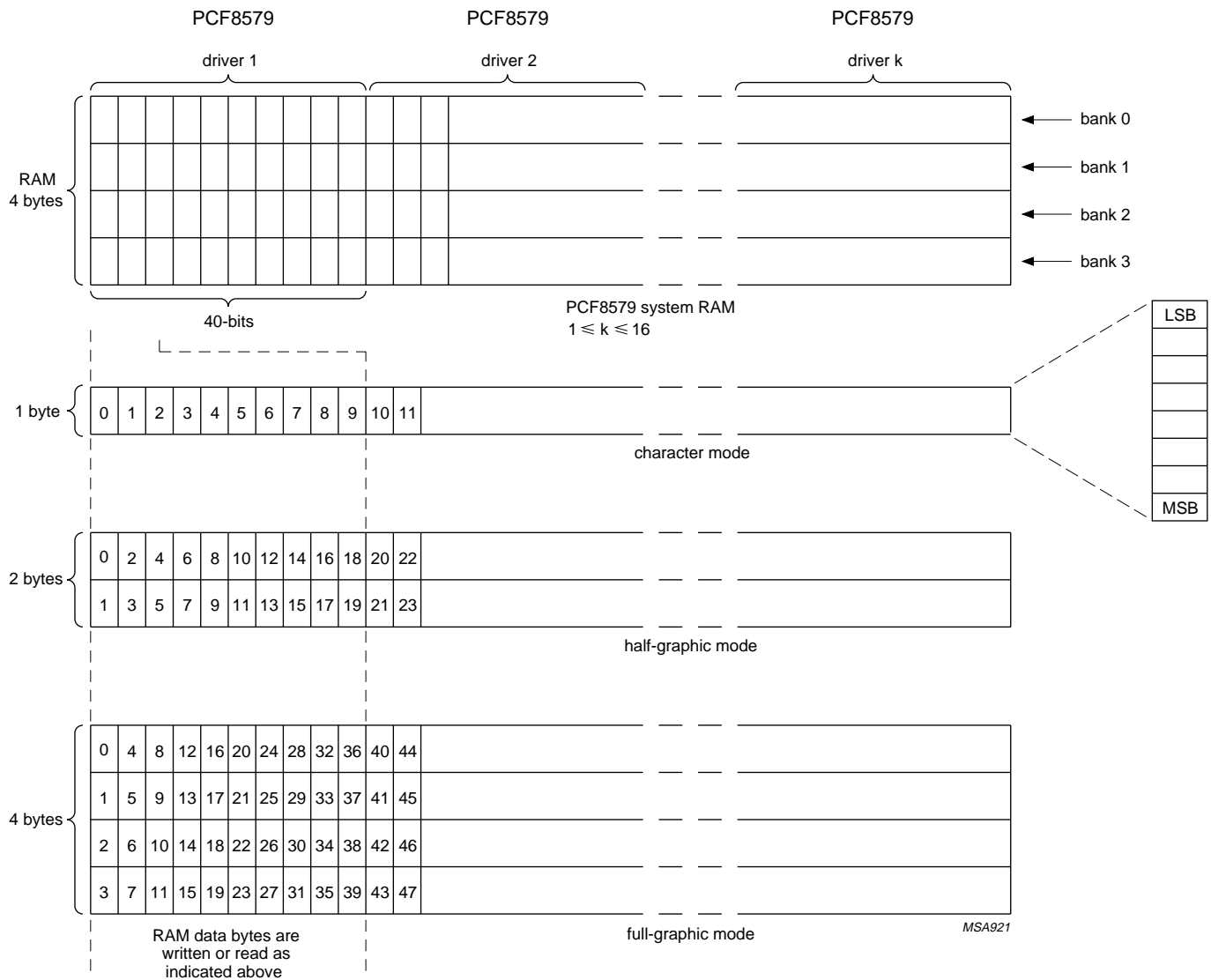


Fig.8 RAM access mode.

LCD column driver for dot matrix graphic displays

PCF8579

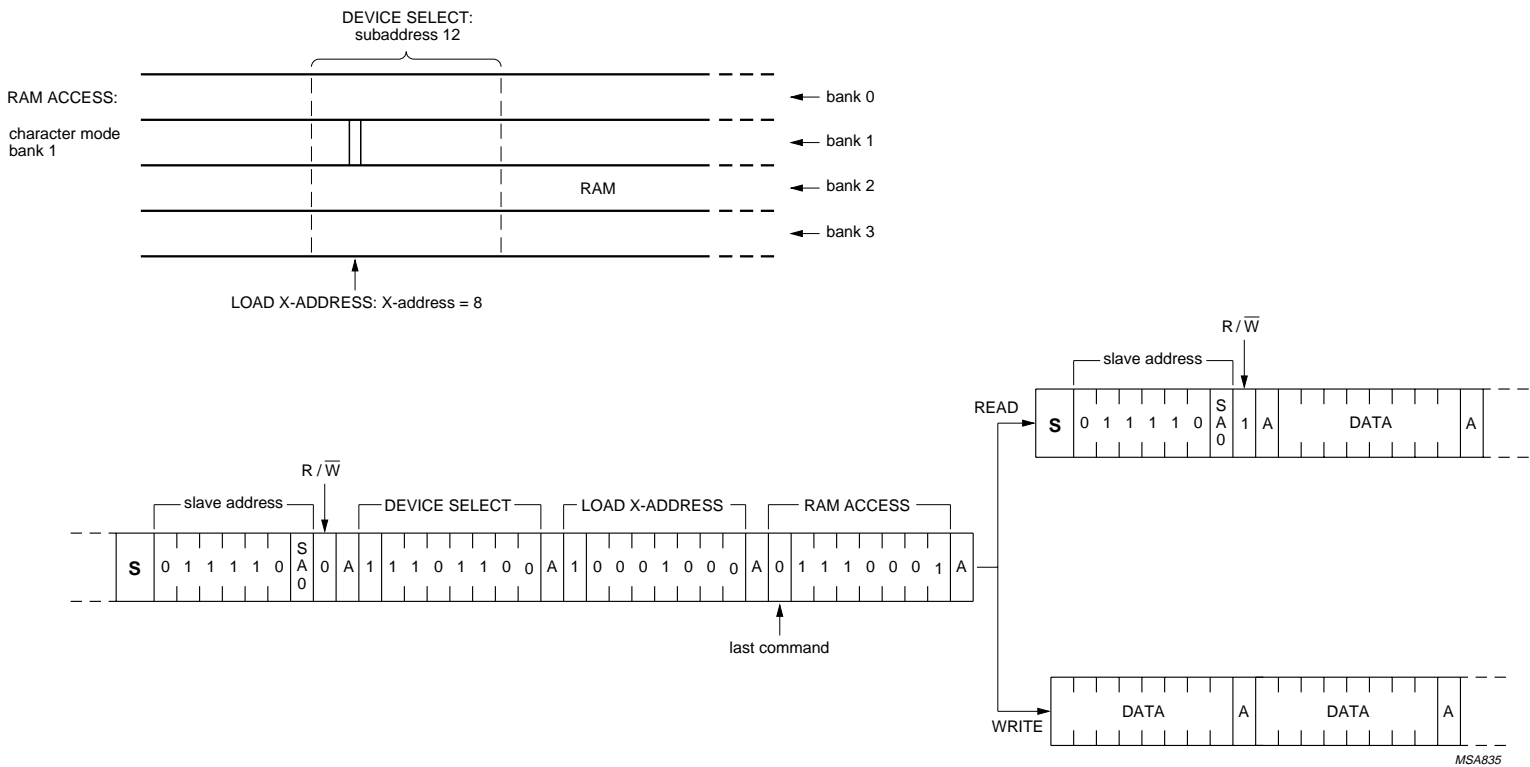


Fig.9 Example of commands specifying initial data byte RAM locations.

LCD column driver for dot matrix graphic displays

PCF8579

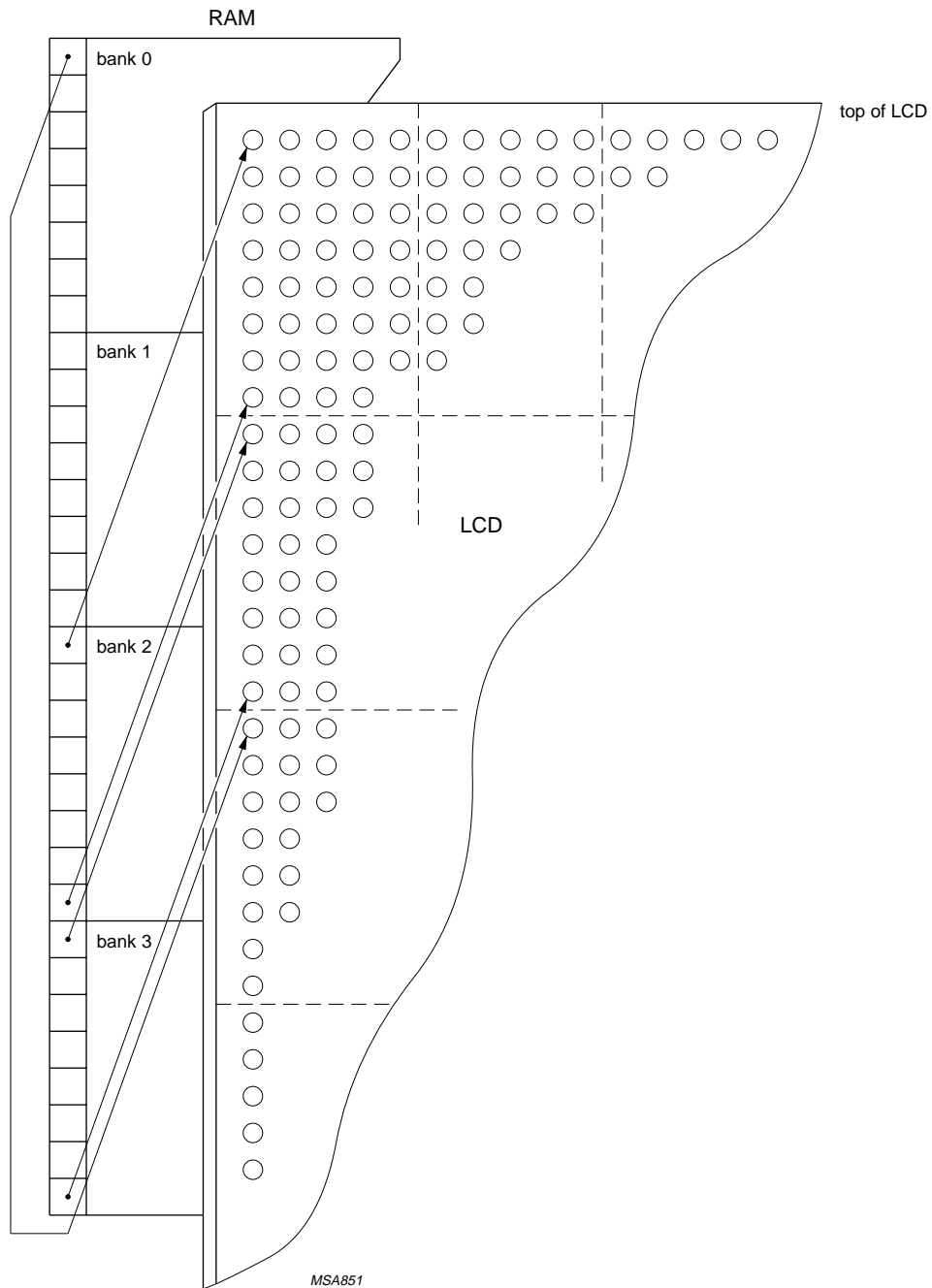


Fig.10 Relationship between display and SET START BANK; 1 : 32 multiplex rate and start bank = 2.

LCD column driver for dot matrix graphic displays

PCF8579

8 I²C-BUS PROTOCOL

Two 7-bit slave addresses (0111100 and 0111101) are reserved for both the PCF8578 and PCF8579. The least significant bit of the slave address is set by connecting input SA0 to either logic 0 (V_{SS}) or logic 1 (V_{DD}). Therefore, two types of PCF8578 or PCF8579 can be distinguished on the same I²C-bus which allows:

1. One PCF8578 to operate with up to 32 PCF8579s on the same I²C-bus for very large applications.
2. The use of two types of LCD multiplex schemes on the same I²C-bus.

In most applications the PCF8578 will have the same slave address as the PCF8579.

The I²C-bus protocol is shown in Fig.11.

All communications are initiated with a start condition (S) from the I²C-bus master, which is followed by the desired slave address and read/write bit. All devices with this slave address acknowledge in parallel. All other devices ignore the bus transfer.

In WRITE mode (indicated by setting the read/write bit LOW) one or more commands follow the slave address acknowledgement. The commands are also acknowledged by all addressed devices on the bus.

The last command must clear the continuation bit C. After the last command a series of data bytes may follow.

The acknowledgement after each byte is made only by the (A0, A1, A2 and A3) addressed PCF8579 or PCF8578 with its implicit subaddress 0. After the last data byte has been acknowledged, the I²C-bus master issues a stop condition (P).

In READ mode, indicated by setting the read/write bit HIGH, data bytes may be read from the RAM following the slave address acknowledgement. After this acknowledgement the master transmitter becomes a master receiver and the PCF8579 becomes a slave transmitter. The master receiver must acknowledge the reception of each byte in turn. The master receiver must signal an end of data to the slave transmitter, by **not** generating an acknowledge on the last byte clocked out of the slave. The slave transmitter then leaves the data line HIGH, enabling the master to generate a stop condition (P).

Display bytes are written into, or read from, the RAM at the address specified by the data pointer and subaddress counter. Both the data pointer and subaddress counter are automatically incremented, enabling a stream of data to be transferred either to, or from, the intended devices.

In multiple device applications, the hardware subaddress pins of the PCF8579s (A0 to A3) are connected to V_{SS} or V_{DD} to represent the desired hardware subaddress code. If two or more devices share the same slave address, then each device **must** be allocated a unique hardware subaddress.

LCD column driver for dot matrix graphic displays

PCF8579

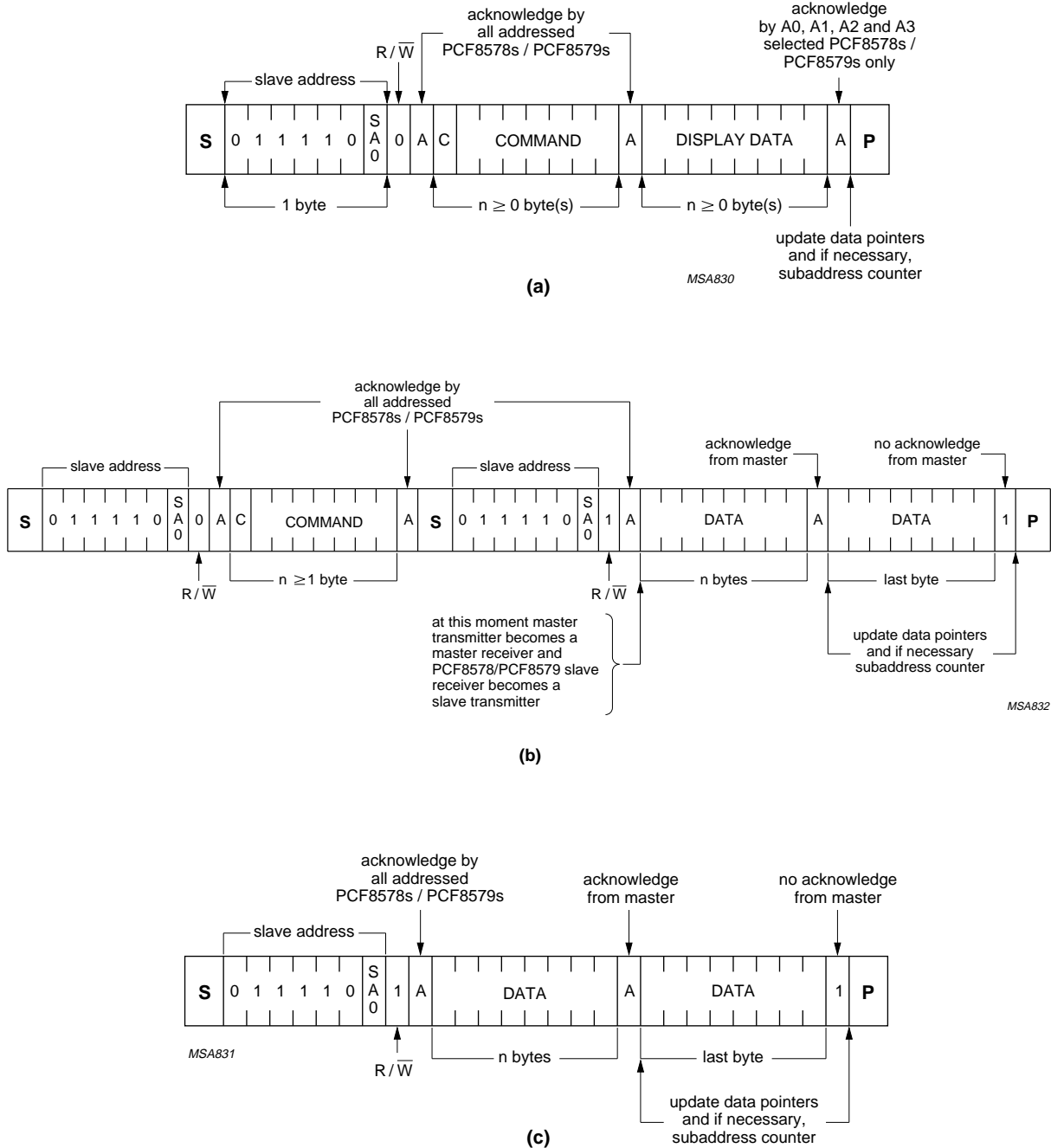


Fig.11 (a) Master transmits to slave receiver (WRITE mode); (b) Master reads after sending command string (WRITE commands; READ data); (c) Master reads slave immediately after sending slave address (READ mode).

LCD column driver for dot matrix graphic displays

PCF8579

8.1 Command decoder

The command decoder identifies command bytes that arrive on the I²C-bus. The most significant bit of a command is the continuation bit C (see Fig.12). When this bit is set, it indicates that the next byte to be transferred will also be a command. If the bit is reset, it indicates the conclusion of the command transfer. Further bytes will be regarded as display data. Commands are transferred in WRITE mode only.

The five commands available to the PCF8579 are defined in Tables 2 and 3.

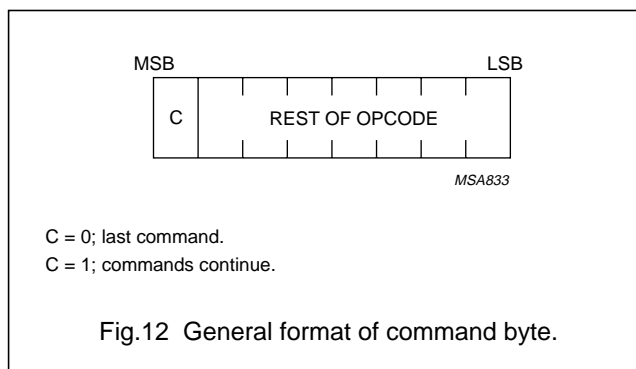


Table 2 Summary of commands

COMMAND	OPCODE ⁽¹⁾	DESCRIPTION
SET MODE	C 1 0 D D D D D	multiplex rate, display status, system type
SET START BANK	C 1 1 1 1 1 D D	defines bank at top of LCD
DEVICE SELECT	C 1 1 0 D D D D	defines device subaddress
RAM ACCESS	C 1 1 1 D D D D	graphic mode, bank select (D D D D ≥ 12 is not allowed; see SET START BANK opcode)
LOAD X-ADDRESS	C 0 D D D D D D	0 to 39

Note

1. C = command continuation bit. D = may be a logic 1 or 0.

LCD column driver for dot matrix graphic displays

PCF8579

Table 3 Definition of PCF8578/PCF8579 commands

COMMAND	OPCODE	OPTIONS	DESCRIPTION
SET MODE	C 1 0 T E1 E0 M1 M0	see Table 4	defines LCD drive mode
		see Table 5	defines display status
		see Table 6	defines system type
SET START BANK	C 1 1 1 1 1 B1 B0	see Table 7	defines pointer to RAM bank corresponding to the top of the LCD; useful for scrolling, pseudo motion and background preparation of new display
DEVICE SELECT	C 1 1 0 A3 A2 A1 A0	see Table 8	four bits of immediate data, bits A0 to A3, are transferred to the subaddress counter to define one of sixteen hardware subaddresses
RAM ACCESS	C 1 1 1 G1 G0 Y1 Y0	see Table 9	defines the auto-increment behaviour of the address for RAM access
		see Table 10	two bits of immediate data, bits Y0 to Y1, are transferred to the X-address pointer to define one of forty display RAM columns
LOAD X-ADDRESS	C 0 X5 X4 X3 X2 X1 X0	see Table 11	six bits of immediate data, bits X0 to X5, are transferred to the X-address pointer to define one of forty display RAM columns

LCD column driver for dot matrix graphic displays

PCF8579

Table 4 Set mode option 1

LCD DRIVE MODE		BITS	
		M1	M0
1 : 8	MUX (8 rows)	0	1
1 : 16	MUX (16 rows)	1	0
1 : 24	MUX (24 rows)	1	1
1 : 32	MUX (32 rows)	0	0

Table 5 Set mode option 2

DISPLAY STATUS	BITS	
	E1	E0
Blank	0	0
Normal	0	1
All segments on	1	0
Inverse video	1	1

Table 6 Set mode option 3

SYSTEM TYPE	BIT T
PCF8578 row only	0
PCF8578 mixed mode	1

Table 7 Set start bank option 1

START BANK POINTER	BITS	
	B1	B0
Bank 0	0	0
Bank 1	0	1
Bank 2	1	0
Bank 3	1	1

Table 8 Device select option 1

DESCRIPTION	BITS			
Decimal value of 0 to 15	A3	A2	A1	A0

Table 9 RAM access option 1

RAM ACCESS MODE	BITS	
	G1	G0
Character	0	0
Half-graphic	0	1
Full-graphic	1	0
Not allowed (note 1)	1	1

Note

1. See opcode for SET START BANK in Table 3.

Table 10 RAM access option 2

DESCRIPTION	BITS	
Decimal value of 0 to 3	Y1	Y0

Table 11 Load X-address option 1

DESCRIPTION	BITS					
Decimal value of 0 to 39	X5	X4	X3	X2	X1	X0

LCD column driver for dot matrix graphic displays

PCF8579

9 CHARACTERISTICS OF THE I²C-BUS

The I²C-bus is for bidirectional, two-line communication between different ICs or modules. The two lines are a serial data line (SDA) and a serial clock line (SCL) which must be connected to a positive supply via a pull-up resistor. Data transfer may be initiated only when the bus is not busy.

9.1 Bit transfer

One data bit is transferred during each clock pulse. The data on the SDA line must remain stable during the HIGH period of the clock pulse as changes in the data line at this moment will be interpreted as control signals.

9.2 Start and stop conditions

Both data and clock lines remain HIGH when the bus is not busy. A HIGH-to-LOW transition of the data line, while the clock is HIGH, is defined as the start condition (S). A LOW-to-HIGH transition of the data line while the clock is HIGH, is defined as the stop condition (P).

9.3 System configuration

A device transmitting a message is a 'transmitter', a device receiving a message is the 'receiver'. The device that controls the message flow is the 'master' and the devices which are controlled by the master are the 'slaves'.

9.4 Acknowledge

The number of data bytes transferred between the start and stop conditions from transmitter to receiver is unlimited. Each data byte of eight bits is followed by one acknowledge bit. The acknowledge bit is a HIGH level put on the bus by the transmitter, whereas the master generates an extra acknowledge related clock pulse. A slave receiver which is addressed must generate an acknowledge after the reception of each byte. Also a master must generate an acknowledge after the reception of each byte that has been clocked out of the slave transmitter. The device that acknowledges must pull down the SDA line during the acknowledge clock pulse, so that the SDA line is stable LOW during the HIGH period of the acknowledge related clock pulse (set-up and hold times must be taken into consideration). A master receiver must signal the end of a data transmission to the transmitter by **not** generating an acknowledge on the last byte that has been clocked out of the slave. In this event the transmitter must leave the data line HIGH to enable the master to generate a stop condition.

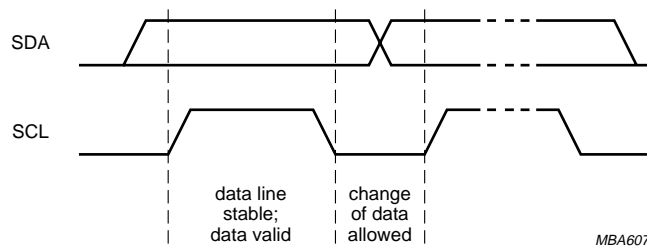
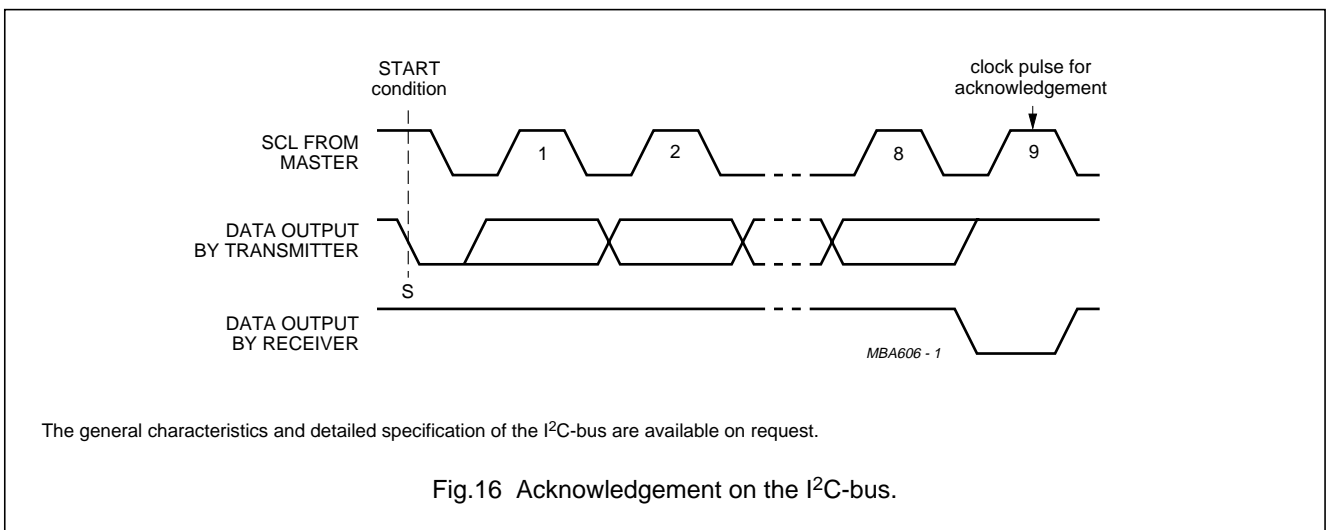
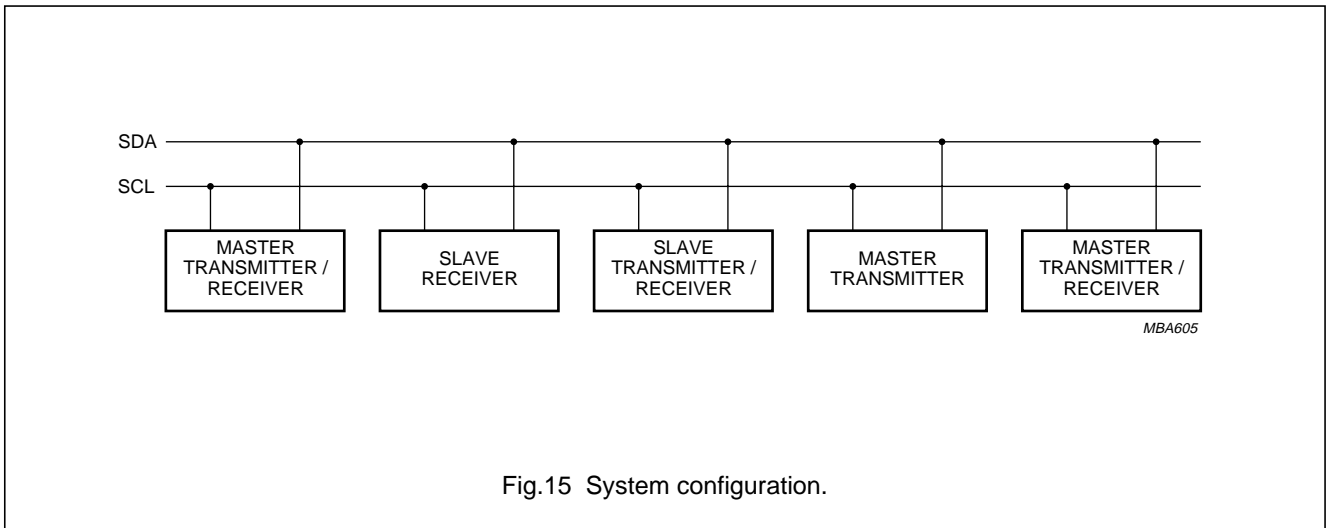
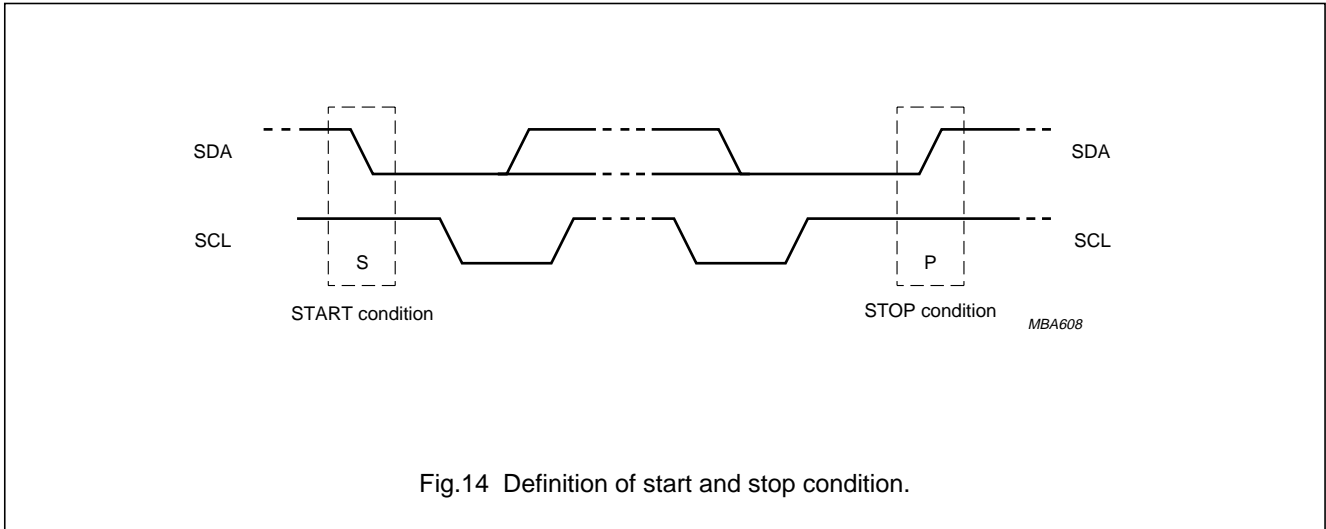


Fig.13 Bit transfer.

LCD column driver for dot matrix graphic displays

PCF8579



LCD column driver for dot matrix graphic displays

PCF8579

10 LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
V_{DD}	supply voltage	-0.5	+8.0	V
V_{LCD}	LCD supply voltage	$V_{DD} - 11$	V_{DD}	V
V_{i1}	input voltage pins SDA, SCL, \overline{SYNC} , CLK, TEST, SA0, A0, A1, A2 and A3	$V_{SS} - 0.5$	$V_{DD} + 0.5$	V
V_{i2}	input voltage pins V_3 and V_4	$V_{LCD} - 0.5$	$V_{DD} + 0.5$	V
V_{o1}	output voltage pin SDA	$V_{SS} - 0.5$	$V_{DD} + 0.5$	V
V_{o2}	output voltage pins C0 to C39	$V_{LCD} - 0.5$	$V_{DD} + 0.5$	V
I_I	DC input current	-10	+10	mA
I_O	DC output current	-10	+10	mA
I_{DD}, I_{SS}, I_{LCD}	current at pins V_{DD} , V_{SS} or V_{LCD}	-50	+50	mA
P_{tot}	total power dissipation per package	-	400	mW
P_o	power dissipation per output	-	100	mW
T_{stg}	storage temperature	-65	+150	°C

11 HANDLING

Inputs and outputs are protected against electrostatic discharge in normal handling. However, to be totally safe it is desirable to take normal precautions appropriate to handling MOS devices. Advice can be found in Data Handbook IC12 under "Handling MOS Devices".

LCD column driver for dot matrix graphic displays

PCF8579

12 DC CHARACTERISTICS

$V_{DD} = 2.5$ to 6 V; $V_{SS} = 0$ V; $V_{LCD} = V_{DD} - 3.5$ V to $V_{DD} - 9$ V; $T_{amb} = -40$ to $+85$ °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supplies						
V_{DD}	supply voltage		2.5	–	6.0	V
V_{LCD}	LCD supply voltage		$V_{DD} - 9$	–	$V_{DD} - 3.5$	V
I_{DD}	supply current	$f_{CLK} = 2$ kHz; note 1	–	9	20	μ A
V_{POR}	power-on reset level	note 2	–	1.3	1.8	V
Logic						
V_{IL}	LOW level input voltage		V_{SS}	–	$0.3V_{DD}$	V
V_{IH}	HIGH level input voltage		$0.7V_{DD}$	–	V_{DD}	V
I_{LI1}	leakage current at pins SDA, SCL, SYNC, CLK, TEST, SA0, A0, A1, A2 and A3	$V_i = V_{DD}$ or V_{SS}	–1	–	+1	μ A
I_{OL}	LOW level output current at pin SDA	$V_{OL} = 0.4$ V; $V_{DD} = 5$ V	3	–	–	mA
C_i	input capacitance	note 3	–	–	5	pF
LCD outputs						
I_{LI2}	leakage current at pins V_3 to V_4	$V_i = V_{DD}$ or V_{LCD}	–2	–	+2	μ A
V_{DC}	DC component of LCD drivers pins C0 to C39		–	± 20	–	mV
R_{COL}	output resistance at pins C0 to C39	note 4	–	3	6	k Ω

Notes

- Outputs are open; inputs at V_{DD} or V_{SS} ; I²C-bus inactive; clock with 50% duty factor.
- Resets all logic when $V_{DD} < V_{POR}$.
- Periodically sampled; not 100% tested.
- Resistance measured between output terminal (C0 to C39) and bias input (V_3 , V_4 , V_{DD} and V_{LCD}) when the specified current flows through one output under the following conditions (see Table 1):
 - $V_{op} = V_{DD} - V_{LCD} = 9$ V;
 - $V_3 - V_{LCD} \geq 4.70$ V; $V_4 - V_{LCD} \leq 4.30$ V; $I_{LOAD} = 100$ μ A.

LCD column driver for dot matrix graphic displays

PCF8579

13 AC CHARACTERISTICS

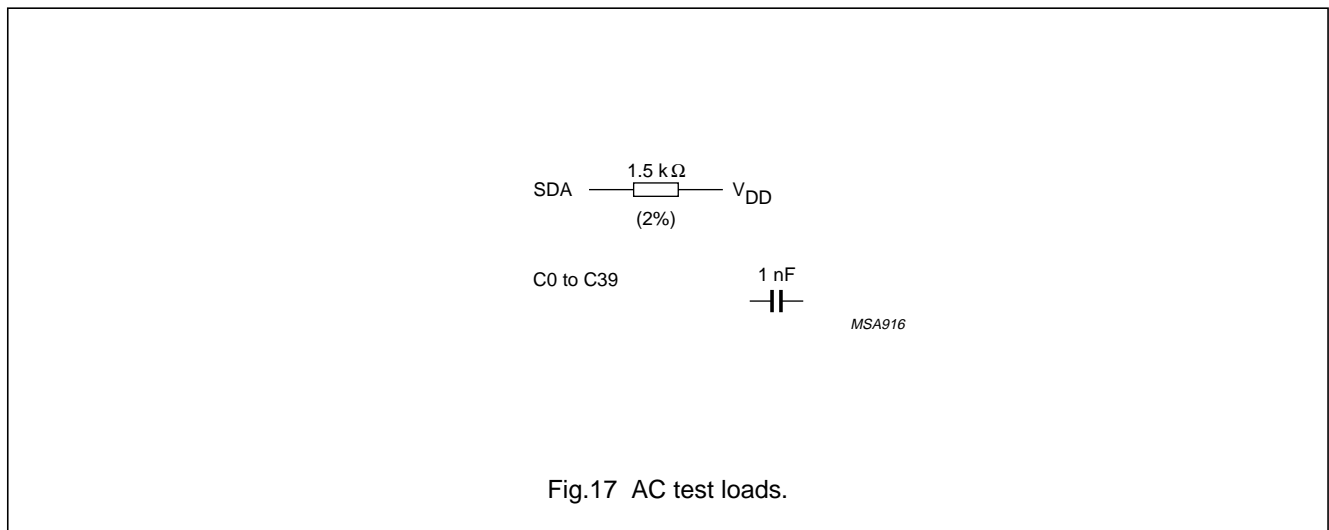
All timing values are referred to V_{IH} and V_{IL} levels with an input voltage swing of V_{SS} to V_{DD} .

$V_{DD} = 2.5$ to 6 V; $V_{SS} = 0$ V; $V_{LCD} = V_{DD} - 3.5$ V to $V_{DD} - 9$ V; $T_{amb} = -40$ to $+85$ °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
f_{clk}	clock frequency	50% duty factor	–	note 1	10	kHz
t_{PLCD}	driver delays	$V_{DD} - V_{LCD} = 9$ V; with test loads	–	–	100	μ s
I²C-bus						
f_{SCL}	SCL clock frequency		–	–	100	kHz
t_{SW}	tolerable spike width on bus		–	–	100	ns
t_{BUF}	bus free time		4.7	–	–	μ s
$t_{SU;STA}$	START condition set-up time	repeated start codes only	4.7	–	–	μ s
$t_{HD;STA}$	START condition hold time		4.0	–	–	μ s
t_{LOW}	SCL LOW time		4.7	–	–	μ s
t_{HIGH}	SCL HIGH time		4.0	–	–	μ s
t_r	SCL and SDA rise time		–	–	1.0	μ s
t_f	SCL and SDA fall time		–	–	0.3	μ s
$t_{SU;DAT}$	data set-up time		250	–	–	ns
$t_{HD;DAT}$	data hold time		0	–	–	ns
$t_{SU;STO}$	STOP condition set-up time		4.0	–	–	μ s

Note

- Typically 0.9 to 3.3 kHz.



LCD column driver for dot matrix graphic displays

PCF8579

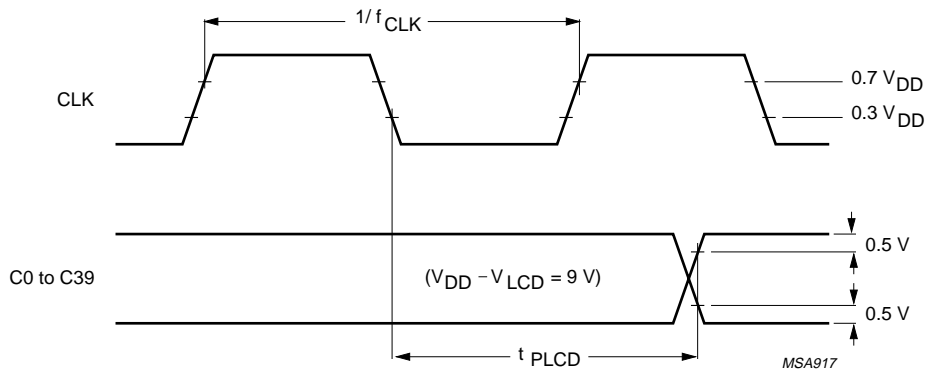


Fig.18 Driver timing waveforms.

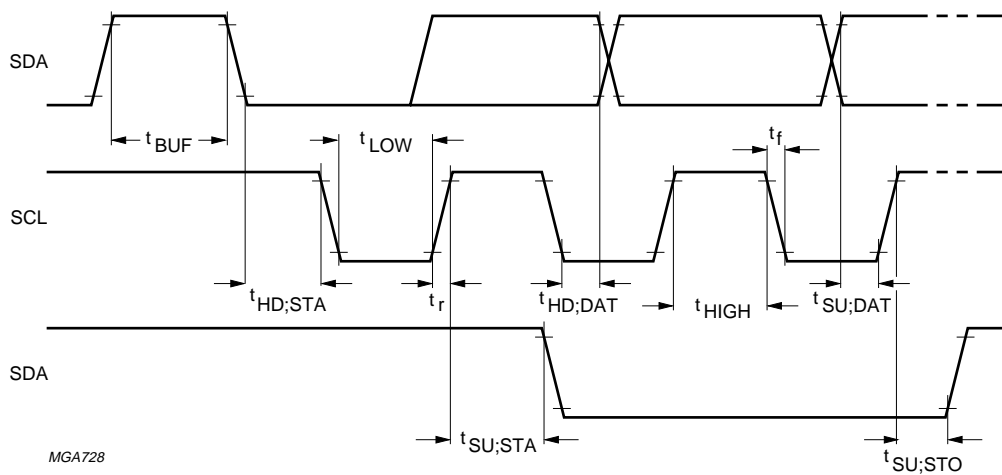


Fig.19 I²C-bus timing waveforms.

LCD column driver for dot matrix graphic displays

PCF8579

14 APPLICATION INFORMATION

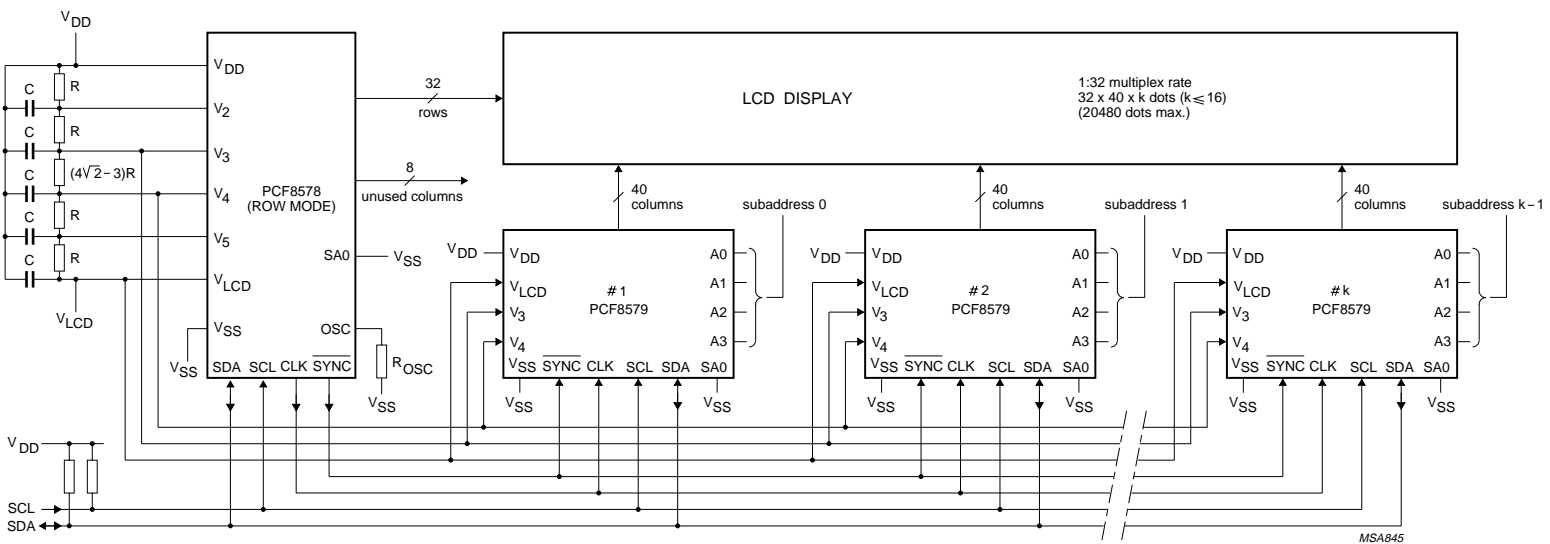


Fig.20 Typical LCD driver system with 1 : 32 multiplex rate.

LCD column driver for dot matrix graphic displays

PCF8579

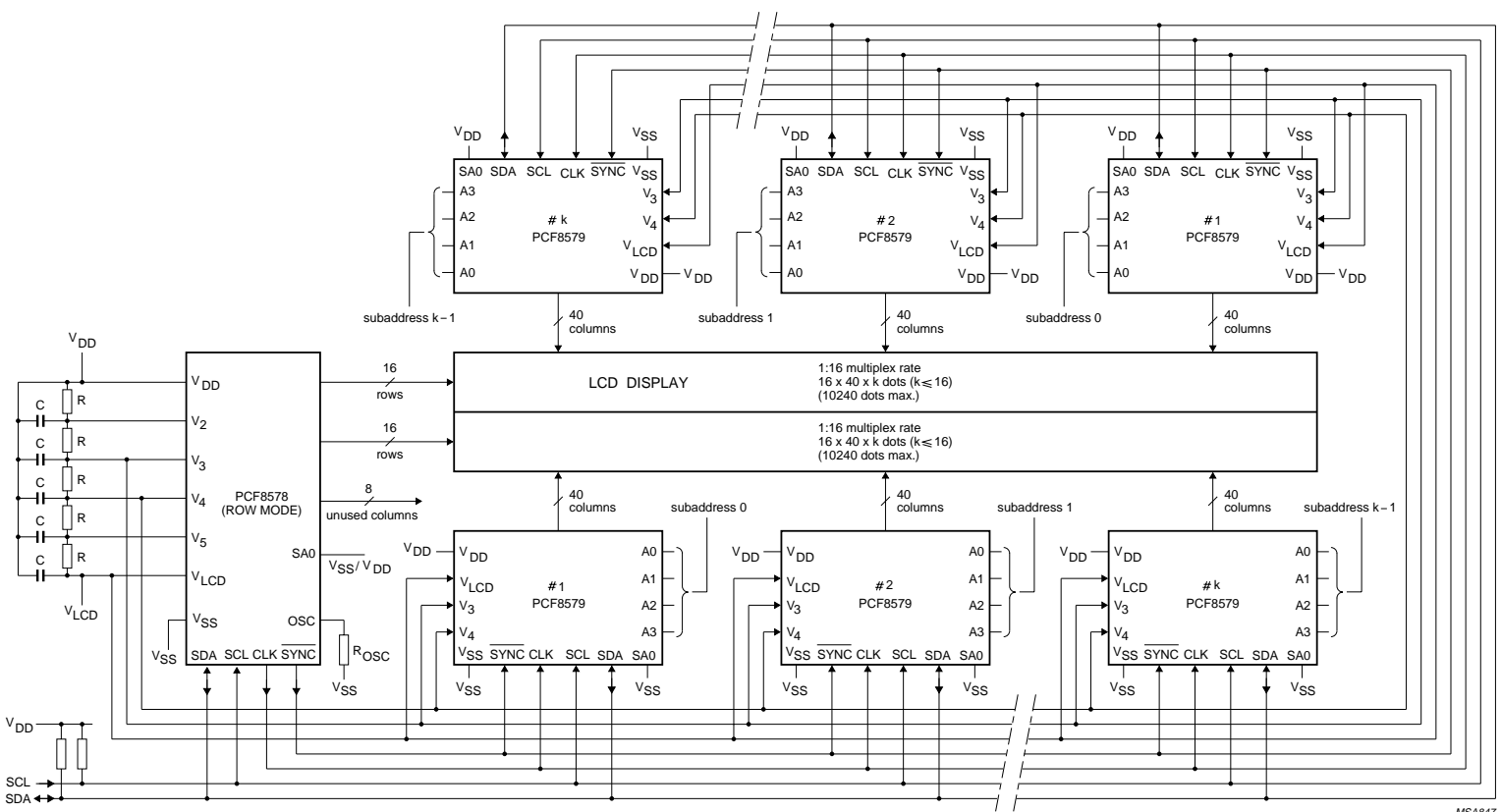


Fig.21 Split screen application with 1 : 16 multiplex rate for improved contrast.

LCD column driver for dot matrix graphic displays

PCF8579

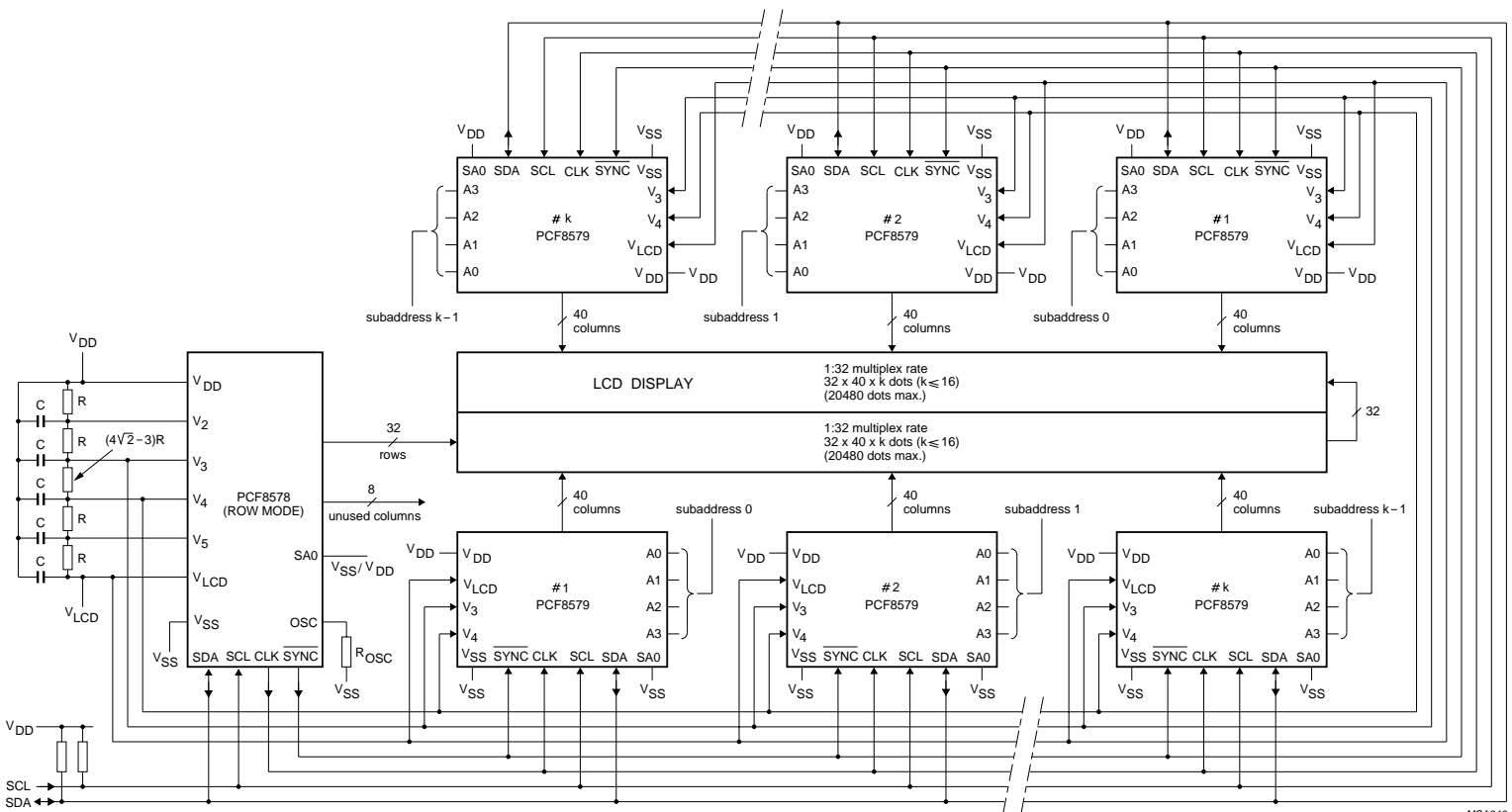


Fig.22 Split screen application with 1 : 32 multiplex rate.

LCD column driver for dot matrix graphic displays

PCF8579

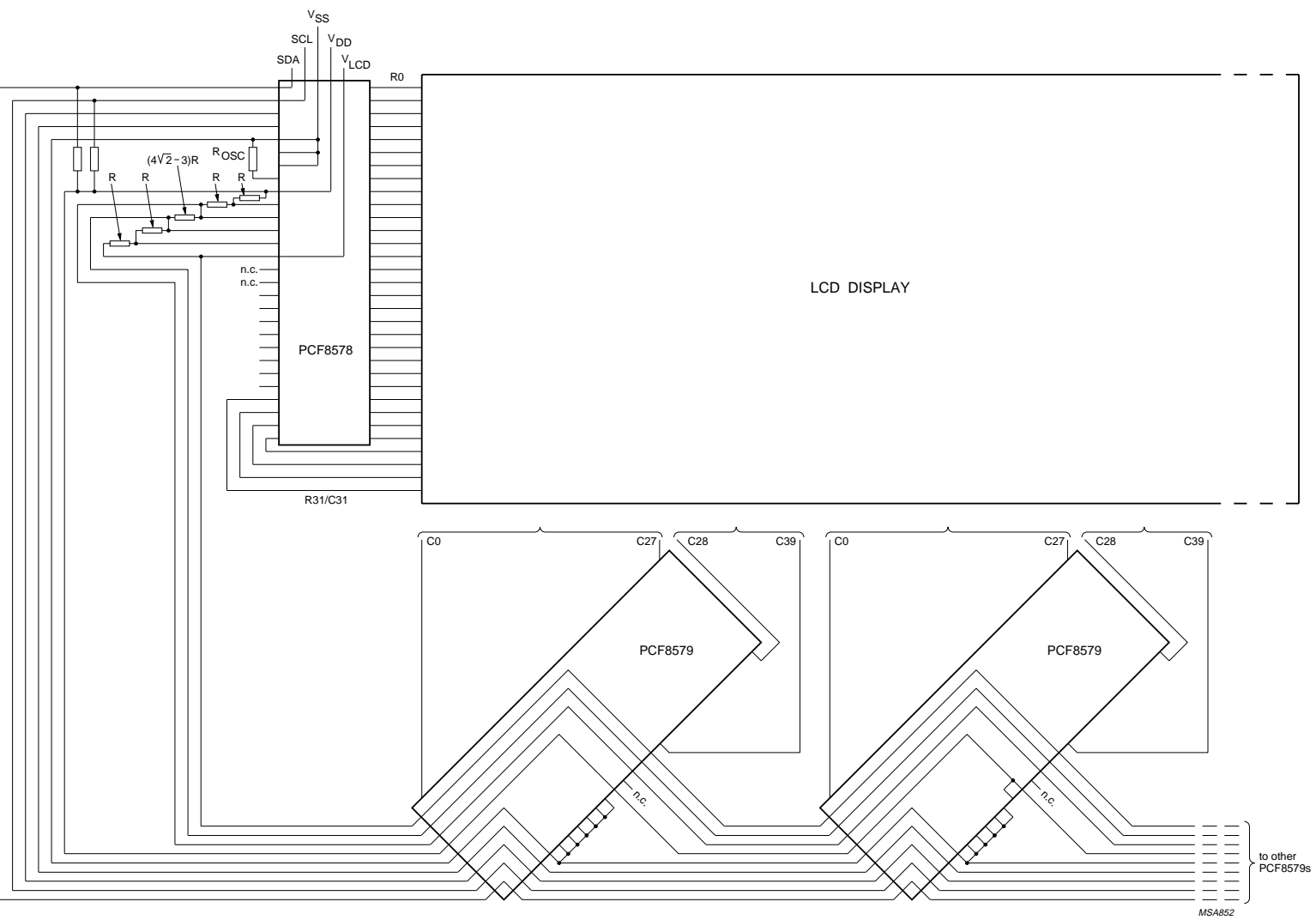
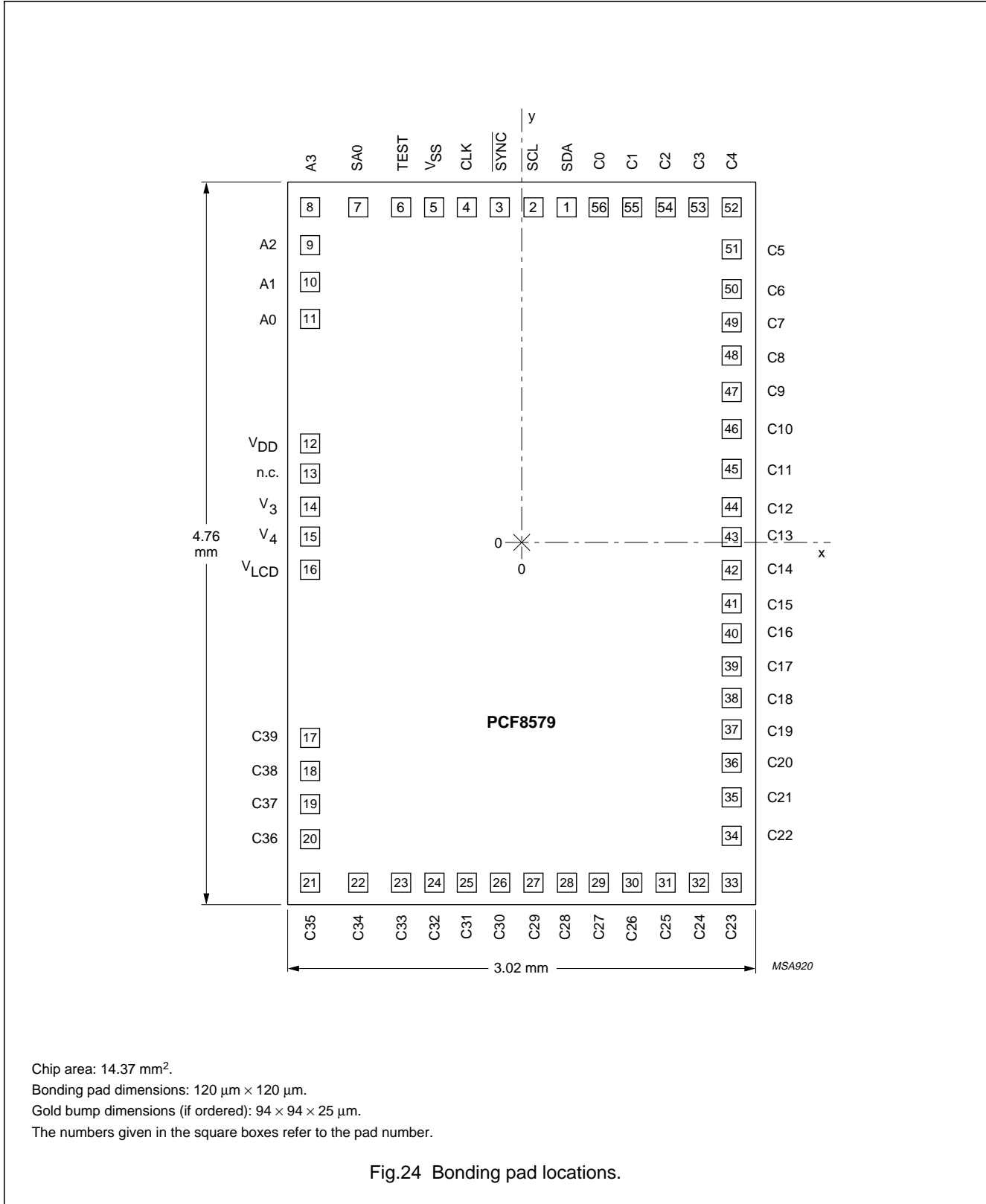


Fig.23 Example of single plane wiring, single screen with 1 : 32 multiplex rate (PCF8578 in row driver mode).

LCD column driver for dot matrix graphic displays

PCF8579

15 CHIP DIMENSIONS AND BONDING PAD LOCATIONS



Chip area: 14.37 mm².
 Bonding pad dimensions: 120 μm × 120 μm.
 Gold bump dimensions (if ordered): 94 × 94 × 25 μm.
 The numbers given in the square boxes refer to the pad number.

Fig.24 Bonding pad locations.

LCD column driver for dot matrix graphic displays

PCF8579

Table 12 Bonding pad locations (dimensions in μm)

All x/y coordinates are referenced to centre of chip, see Fig.24.

PAD NUMBER	SYMBOL	x	y	PINS	
				VSO56	LQFP64
1	SDA	252	2142	1	7
2	SCL	48	2142	2	8
3	$\overline{\text{SYNC}}$	-156	2142	3	9
4	CLK	-360	2142	4	10
5	V_{SS}	-564	2142	5	11
6	TEST	-786	2142	6	12
7	SA0	-1032	2142	7	13
8	A3	-1314	2142	8	14
9	A2	-1314	1920	9	16
10	A1	-1314	1716	10	17
11	A0	-1314	1512	11	18
12	V_{DD}	-1314	708	12	20
13	n.c.	-1314	504	13	21
14	V_3	-1314	300	14	22
15	V_4	-1314	96	15	23
16	V_{LCD}	-1314	-108	16	24
17	C39	-1314	-1308	17	30
18	C38	-1314	-1512	18	31
19	C37	-1314	-1716	19	32
20	C36	-1314	-1920	20	33
21	C35	-1314	-2142	21	35
22	C34	-1032	-2142	22	36
23	C33	-786	-2142	23	37
24	C32	-564	-2142	24	38
25	C31	-360	-2142	25	39
26	C30	-156	-2142	26	40
27	C29	48	-2142	27	41
28	C28	252	-2142	28	42
29	C27	498	-2142	29	43
30	C26	702	-2142	30	44
31	C25	906	-2142	31	45
32	C24	1110	-2142	32	46
33	C23	1314	-2142	33	47
34	C22	1314	-1830	34	48
35	C21	1314	-1570	35	49
36	C20	1314	-1326	36	50
37	C19	1314	-1122	37	51

LCD column driver for dot matrix graphic displays

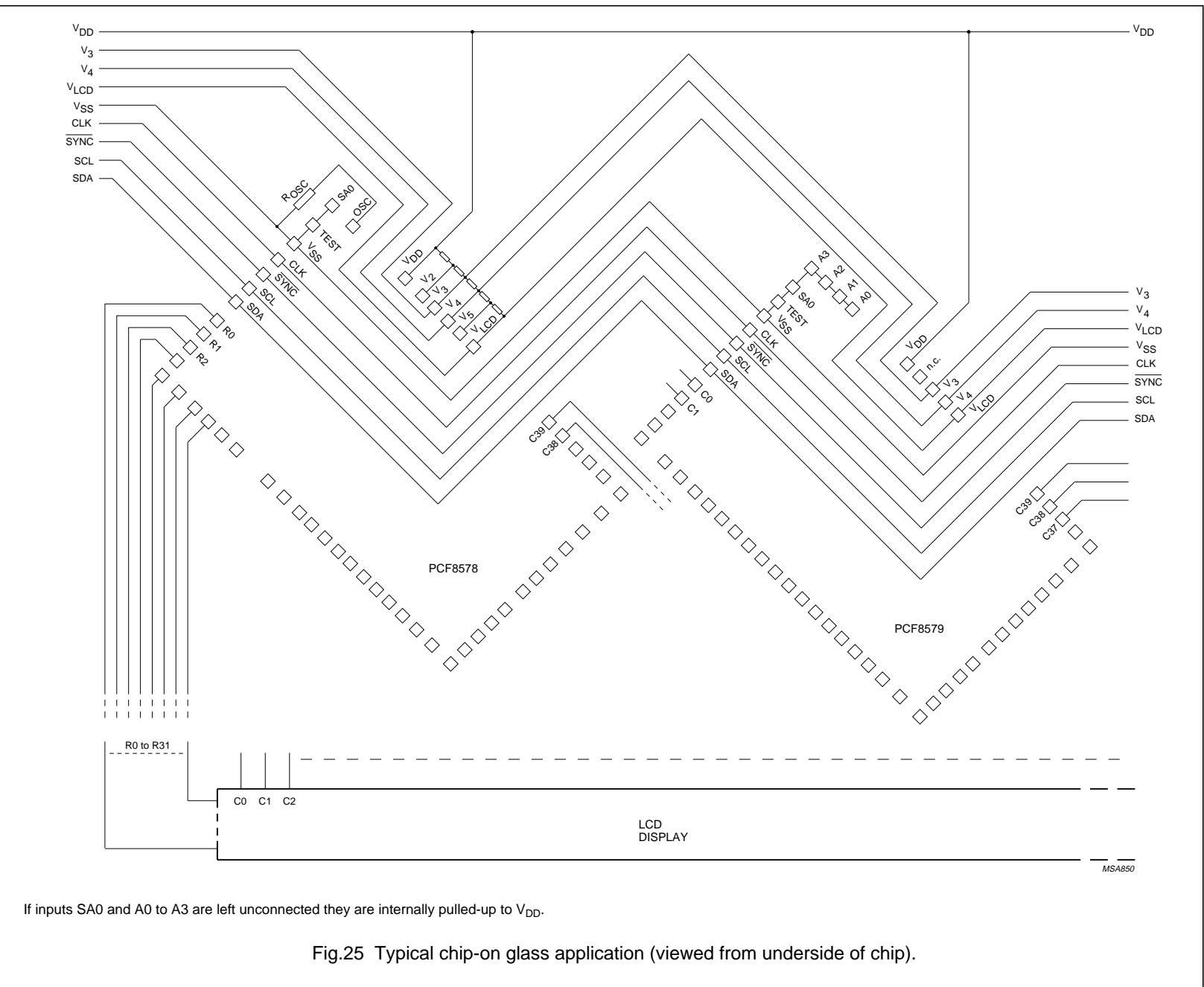
PCF8579

PAD NUMBER	SYMBOL	x	y	PINS	
				VSO56	LQFP64
38	C18	1314	-918	38	52
39	C17	1314	-714	39	53
40	C16	1314	-510	40	54
41	C15	1314	-306	41	55
42	C14	1314	-102	42	56
43	C13	1314	102	43	57
44	C12	1314	306	44	58
45	C11	1314	510	45	59
46	C10	1314	714	46	60
47	C9	1314	918	47	61
48	C8	1314	1122	48	62
49	C7	1314	1326	49	63
50	C6	1314	1566	50	64
51	C5	1314	1830	51	1
52	C4	1314	2142	52	2
53	C3	1110	2142	53	3
54	C2	906	2142	54	4
55	C1	702	2142	55	5
56	C0	498	2142	56	6
-	n.c.	-	-	-	15, 19, 21, 25 to 29, 34

LCD column driver for dot matrix graphic displays

PCF8579

16 CHIP-ON GLASS INFORMATION



If inputs SA0 and A0 to A3 are left unconnected they are internally pulled-up to V_{DD}.

Fig.25 Typical chip-on-glass application (viewed from underside of chip).

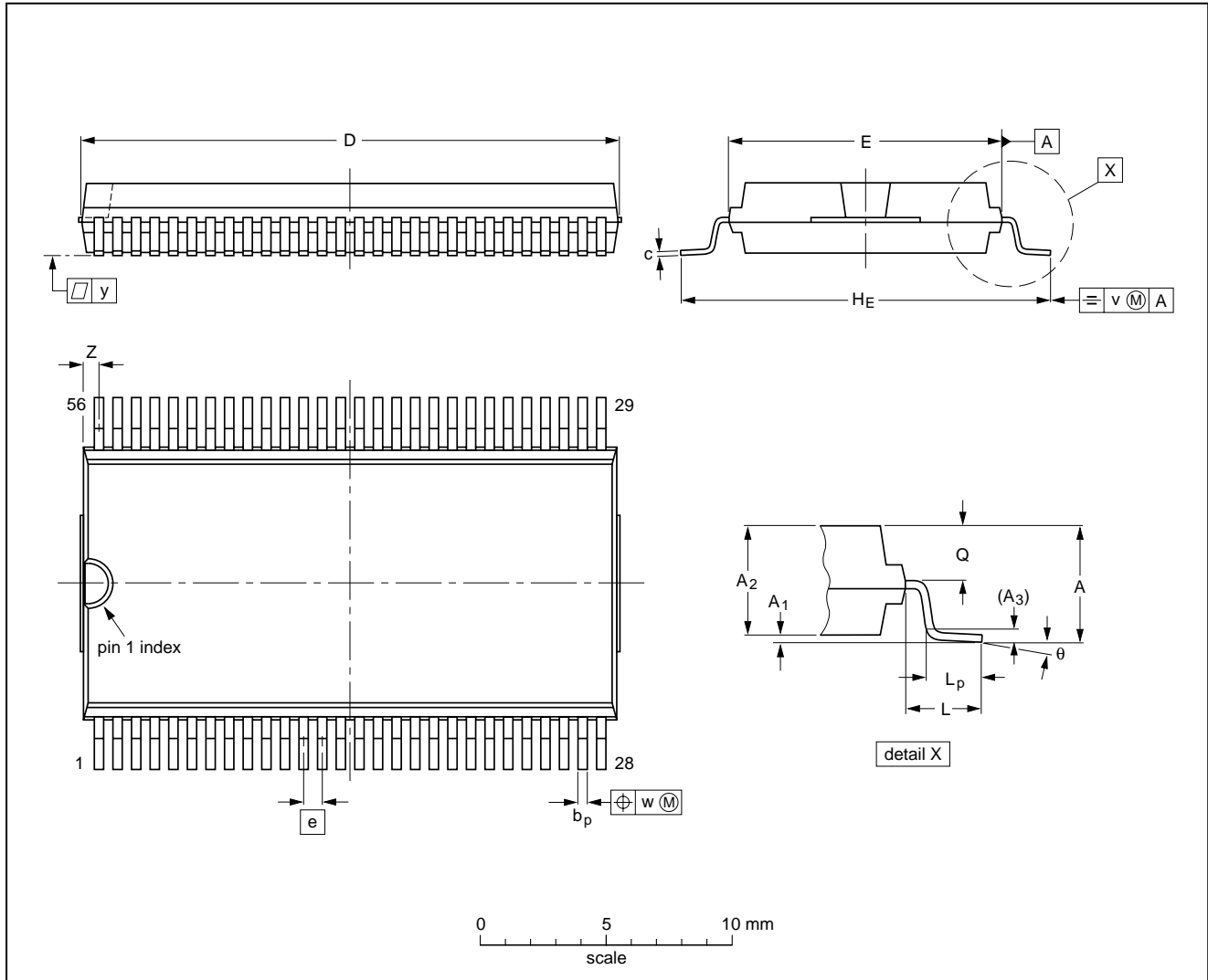
LCD column driver for dot matrix graphic displays

PCF8579

17 PACKAGE OUTLINES

VSO56: plastic very small outline package; 56 leads

SOT190-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	z ⁽¹⁾	θ
mm	3.3	0.3 0.1	3.0 2.8	0.25	0.42 0.30	0.22 0.14	21.65 21.35	11.1 11.0	0.75	15.8 15.2	2.25	1.6 1.4	1.45 1.30	0.2	0.1	0.1	0.90 0.55	7° 0°
inches	0.13	0.012 0.004	0.12 0.11	0.01	0.017 0.012	0.0087 0.0055	0.85 0.84	0.44 0.43	0.0295	0.62 0.60	0.089	0.063 0.055	0.057 0.051	0.008	0.004	0.004	0.035 0.022	

Note

1. Plastic or metal protrusions of 0.3 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

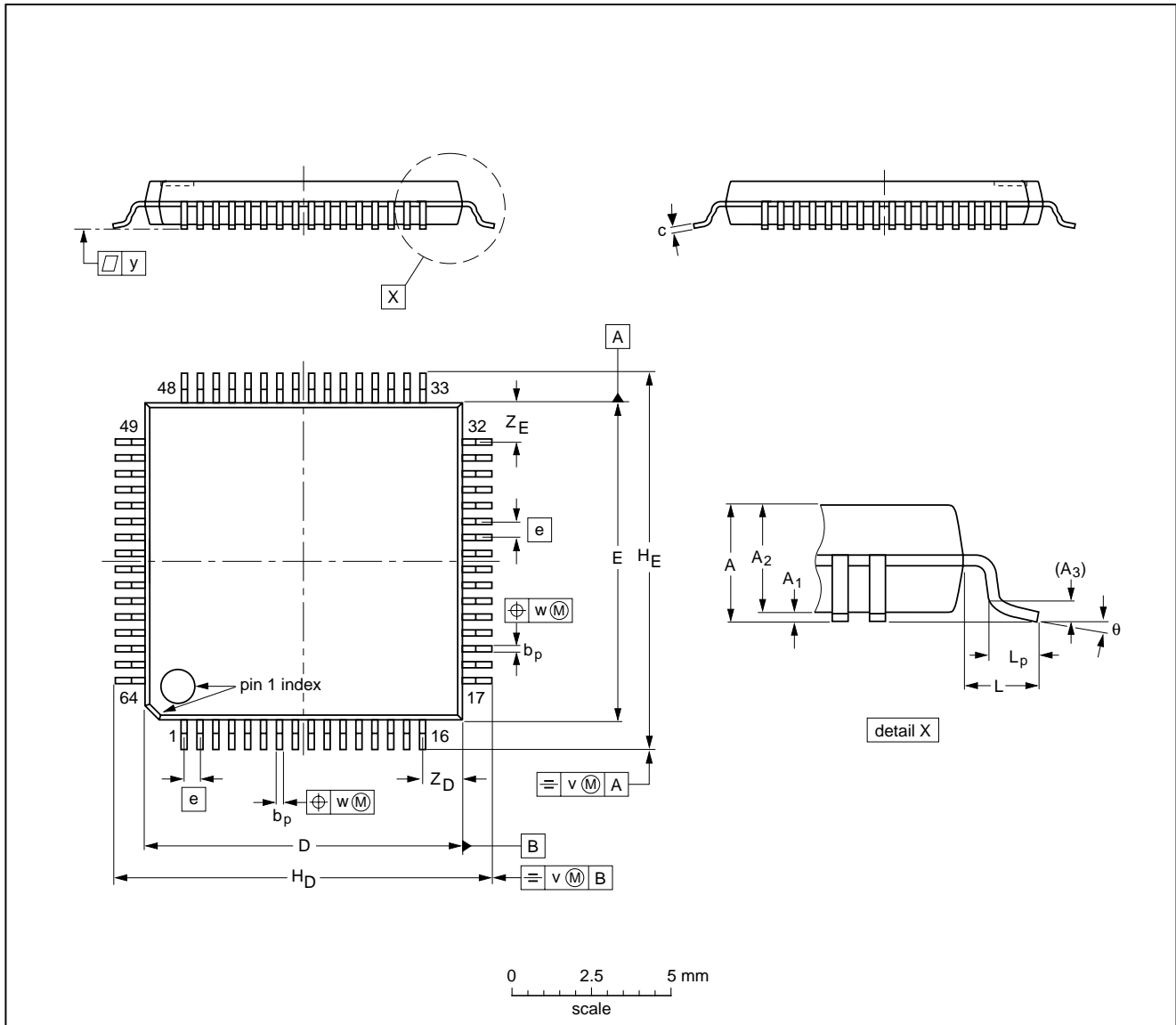
OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT190-1					96-04-02 97-08-11

LCD column driver for dot matrix graphic displays

PCF8579

LQFP64: plastic low profile quad flat package; 64 leads; body 10 x 10 x 1.4 mm

SOT314-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _D	H _E	L	L _p	v	w	y	Z _D ⁽¹⁾	Z _E ⁽¹⁾	θ
mm	1.60	0.20 0.05	1.45 1.35	0.25	0.27 0.17	0.18 0.12	10.1 9.9	10.1 9.9	0.5	12.15 11.85	12.15 11.85	1.0	0.75 0.45	0.2	0.12	0.1	1.45 1.05	1.45 1.05	7° 0°

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT314-2					95-12-19 97-08-01

LCD column driver for dot matrix graphic displays

PCF8579

18 SOLDERING

18.1 Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

18.2 Reflow soldering

Reflow soldering techniques are suitable for all LQFP and VSO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

18.3 Wave soldering

18.3.1 LQFP

Wave soldering is **not** recommended for LQFP packages. This is because of the likelihood of solder bridging due to closely-spaced leads and the possibility of incomplete solder penetration in multi-lead devices.

If wave soldering cannot be avoided, the following conditions must be observed:

- **A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.**

- **The footprint must be at an angle of 45° to the board direction and must incorporate solder thieves downstream and at the side corners.**

Even with these conditions, do not consider wave soldering LQFP packages LQFP48 (SOT313-2), LQFP64 (SOT314-2) or LQFP80 (SOT315-1).

18.3.2 VSO

Wave soldering techniques can be used for all VSO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

18.3.3 METHOD (LQFP AND VSO)

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

18.4 Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

LCD column driver for dot matrix graphic displays

PCF8579

19 DEFINITIONS

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

20 LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

21 PURCHASE OF PHILIPS I²C COMPONENTS



Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.

LCD column driver for dot matrix graphic
displays

PCF8579

NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113,
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 689 211, Fax. +359 2 689 102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,
Tel. +45 32 88 2636, Fax. +45 31 57 1949

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615800, Fax. +358 9 61580/xxx

France: 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex,
Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS,
Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

Hungary: see Austria

India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd.
Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722

Indonesia: see Singapore

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180,
Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,
20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,
Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA,
Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 755 6918, Fax. +7 095 755 6919

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000,
Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Rua do Rocio 220, 5th floor, Suite 51,
04552-903 São Paulo, SÃO PAULO - SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 829 1849

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 3 301 6312, Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: Philips Semiconductors, 6F, No. 96, Chien Kuo N. Rd., Sec. 1,
TAIPEI, Taiwan Tel. +886 2 2134 2870, Fax. +886 2 2134 2874

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,
Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,
Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 625 344, Fax. +381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications,
Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com>

© Philips Electronics N.V. 1997

SCA53

All rights are reserved. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner.

The information presented in this document does not form part of any quotation or contract, is believed to be accurate and reliable and may be changed without notice. No liability will be accepted by the publisher for any consequence of its use. Publication thereof does not convey nor imply any license under patent- or other industrial or intellectual property rights.

Printed in The Netherlands

417067/1200/03/pp40

Date of release: 1997 Apr 01

Document order number: 9397 750 01757

Let's make things better.

Philips
Semiconductors



PHILIPS